



Radiation Issues

CERN Accelerator School – May 2014

- * radiation is everywhere, it can effect electronic systems
 - for dependable operation you cannot ignore this.
 - Particle accelerators actually create radiation fields.
 - certain failure modes are unique to radiation effects

- * radiation effects on electronics are difficult and costly to characterise
 - by far the best thing to do is avoid exposure to radiation.

- * radiation effects are difficult and costly to mitigate
 - by far the best thing to do is avoid exposure to radiation.

1. Context – CERN

2. Radiation – Basic Effects

3. Examples of Radiation Tolerant Design Flow

[An example of a radiation tolerant system in design](#)

The Context...

CERN Accelerator Complex

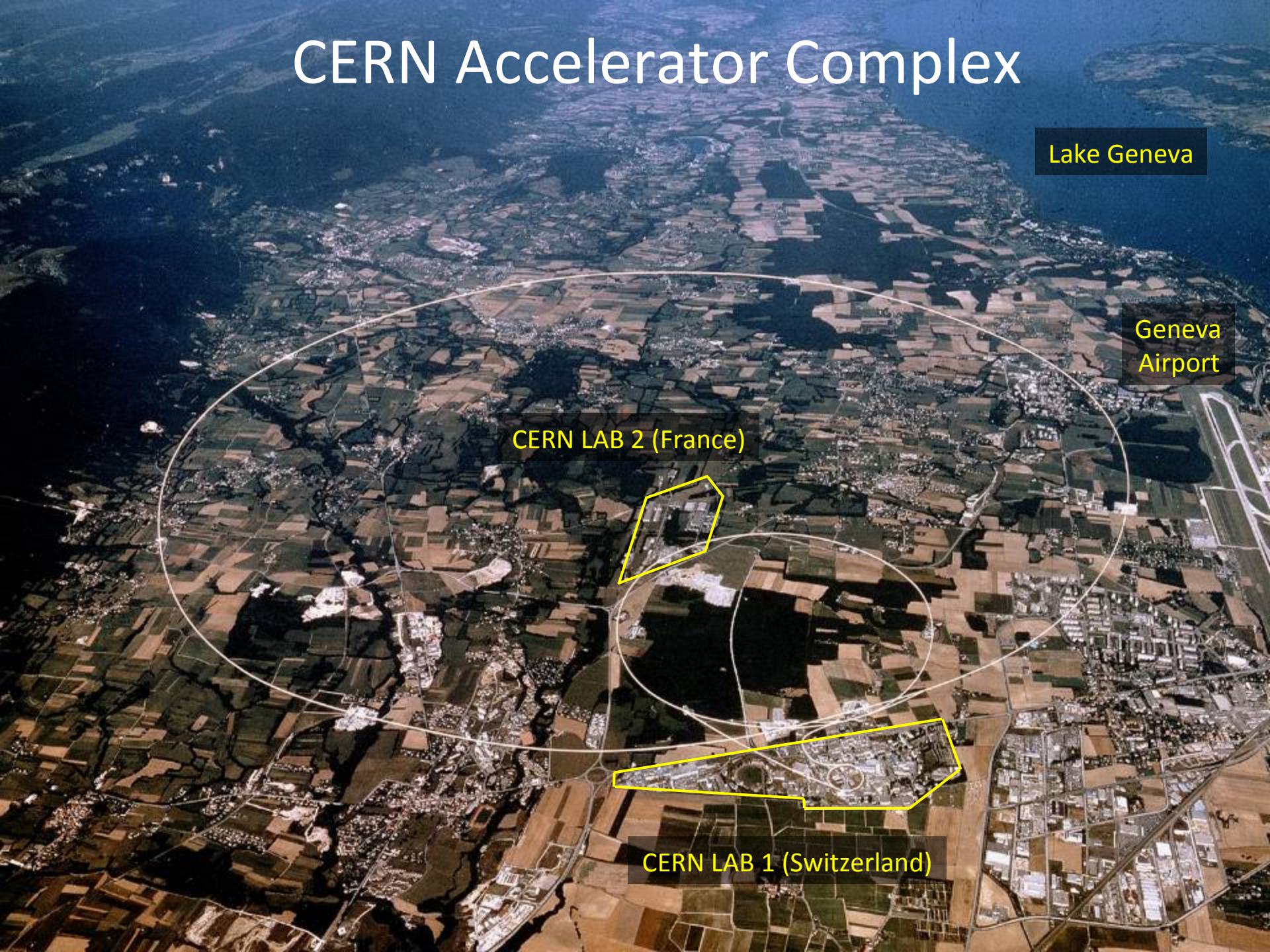
Lake Geneva

Geneva Airport

CERN LAB 2 (France)



CERN LAB 1 (Switzerland)



CERN Accelerator Complex

Large Hadron Collider
(LHC)

Lake Geneva

Geneva
Airport

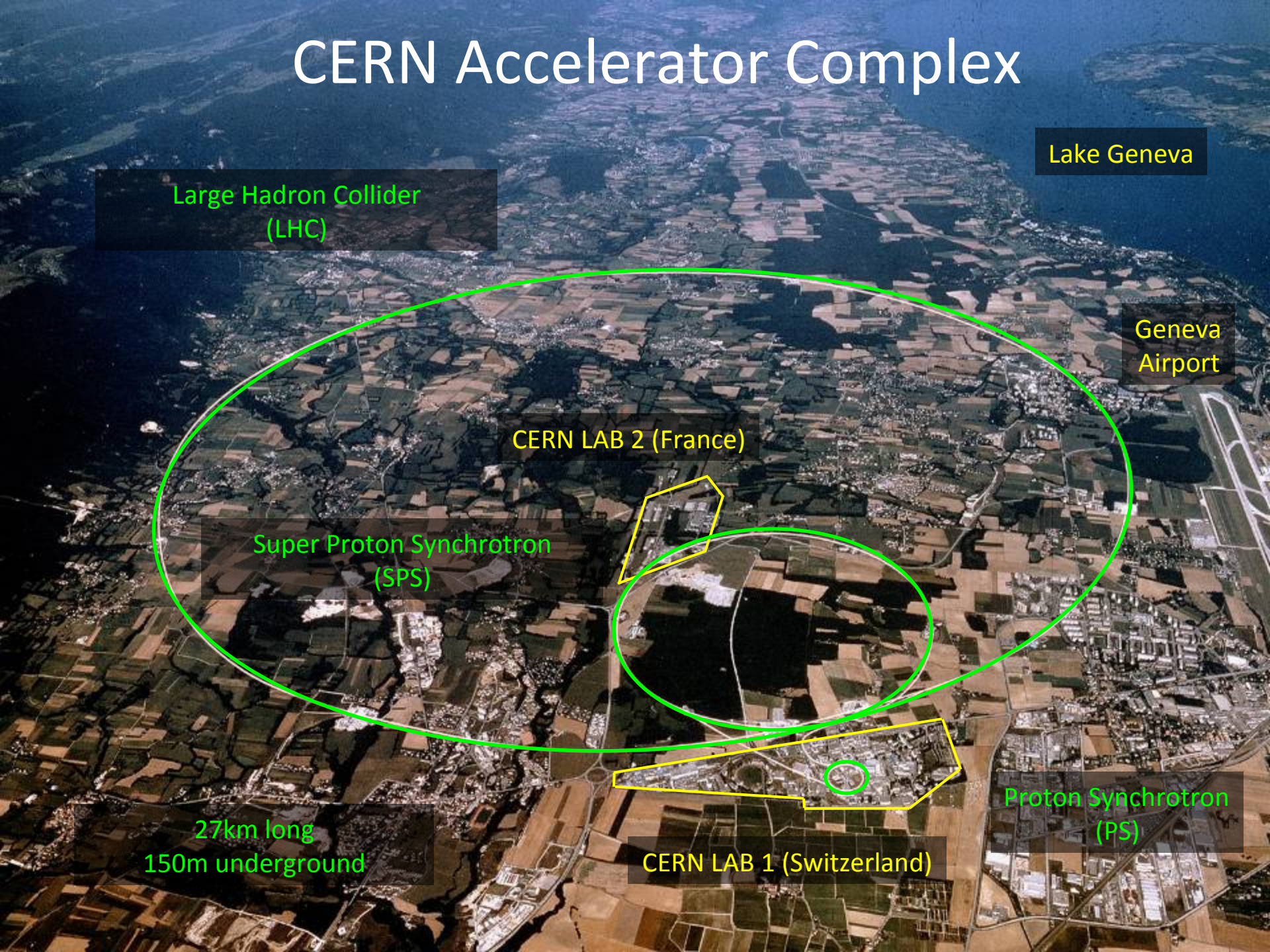
CERN LAB 2 (France)

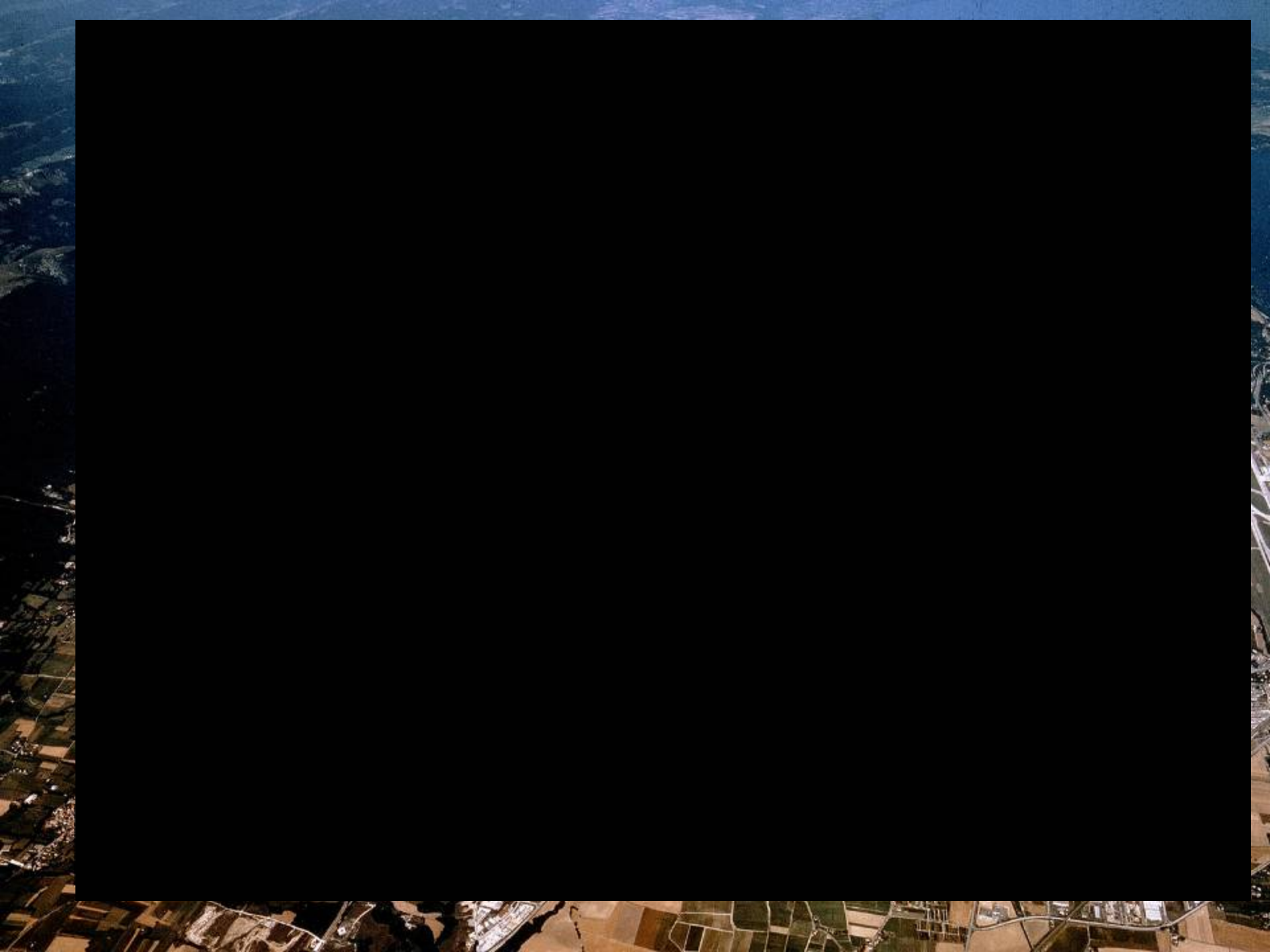
Super Proton Synchrotron
(SPS)

27km long
150m underground

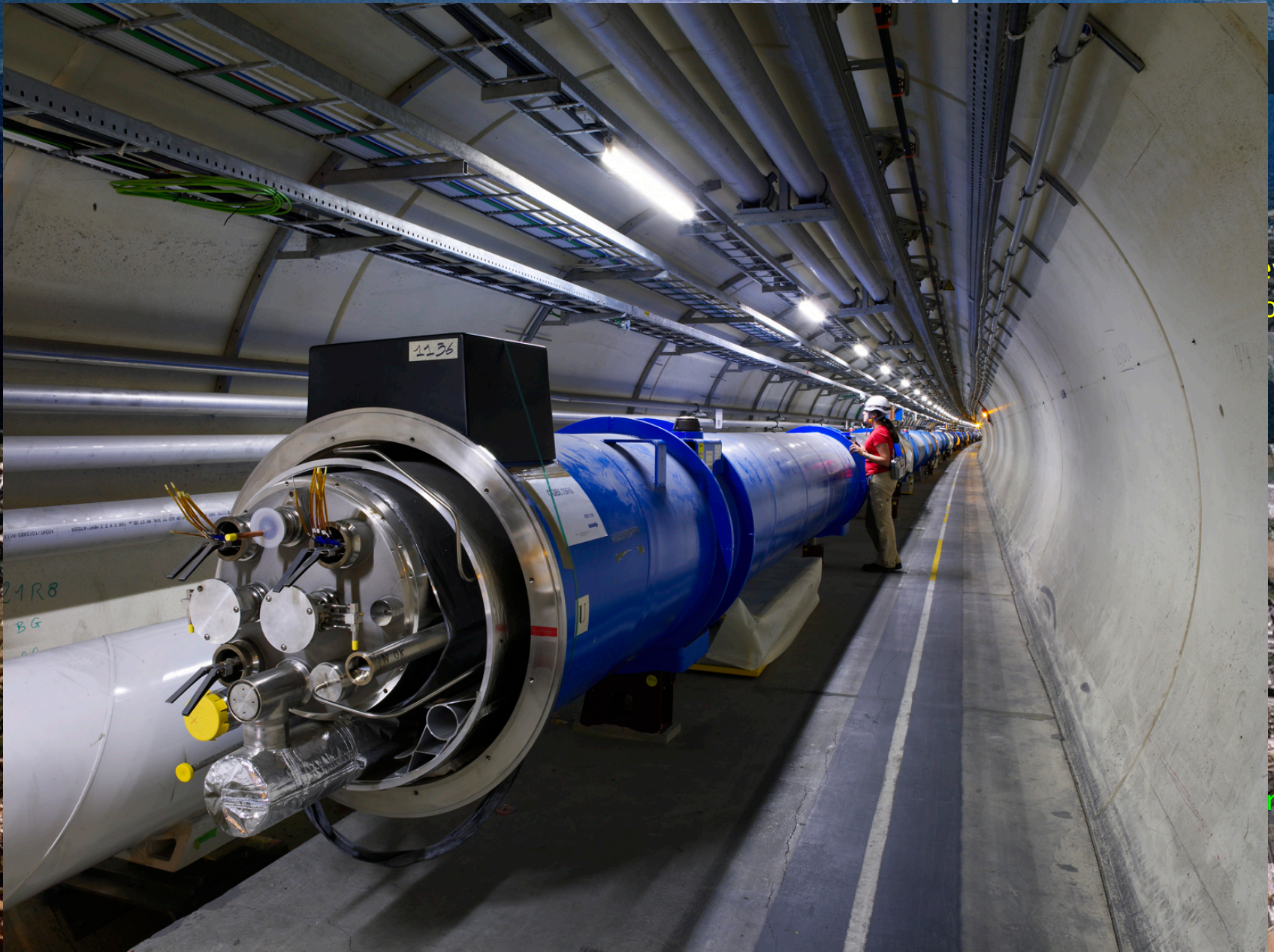
Proton Synchrotron
(PS)

CERN LAB 1 (Switzerland)





CERN Accelerator Complex



eva
ort

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CERN Accelerator Complex



CERN Accelerator Complex

Lake Geneva

Large Hadron Collider
(LHC)

Geneva
Airport

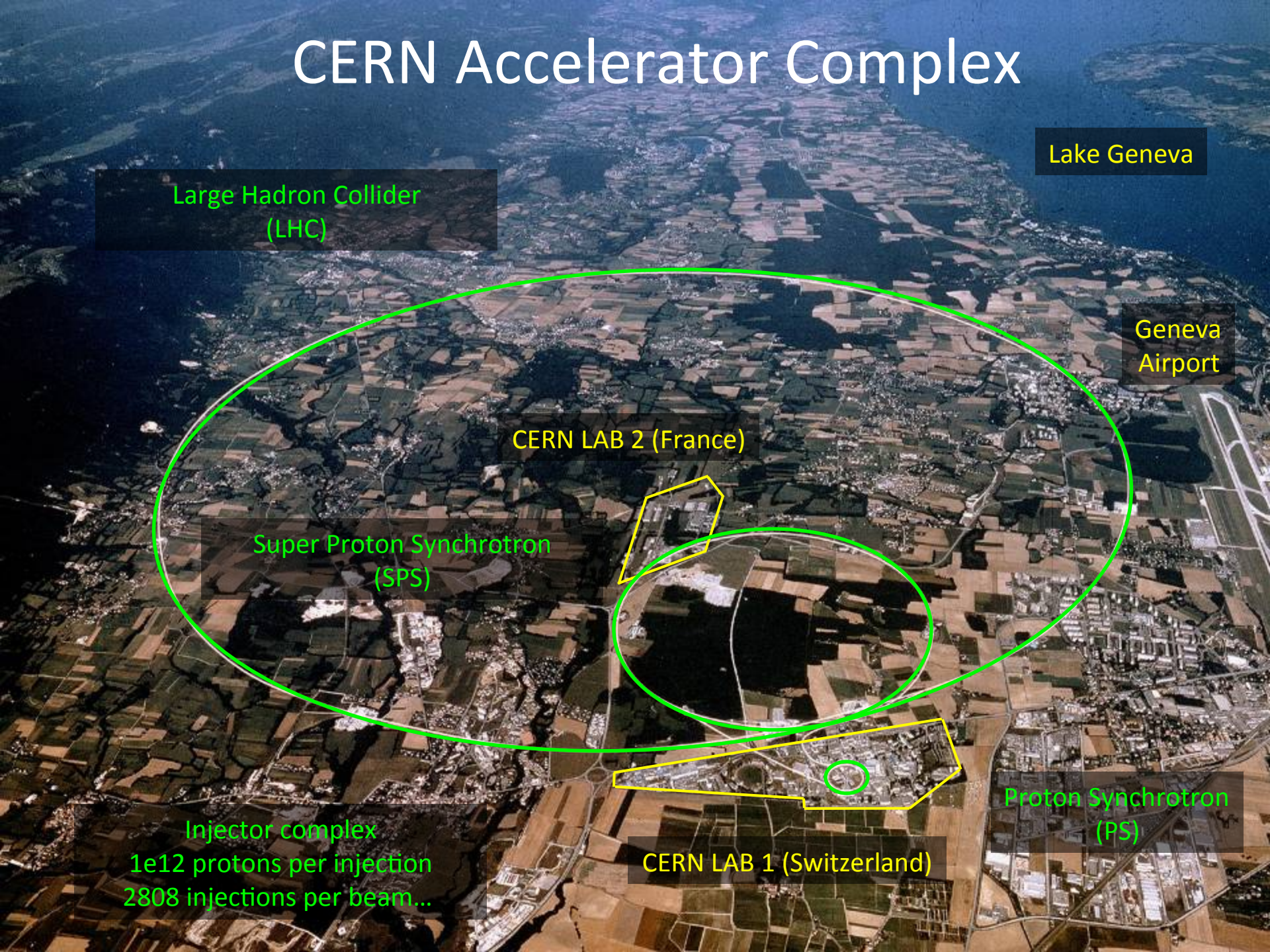
CERN LAB 2 (France)

Super Proton Synchrotron
(SPS)

Injector complex
1e12 protons per injection
2808 injections per beam...

Proton Synchrotron
(PS)

CERN LAB 1 (Switzerland)



CERN Accelerator Complex

Large Hadron Collider
(LHC)

Lake Geneva

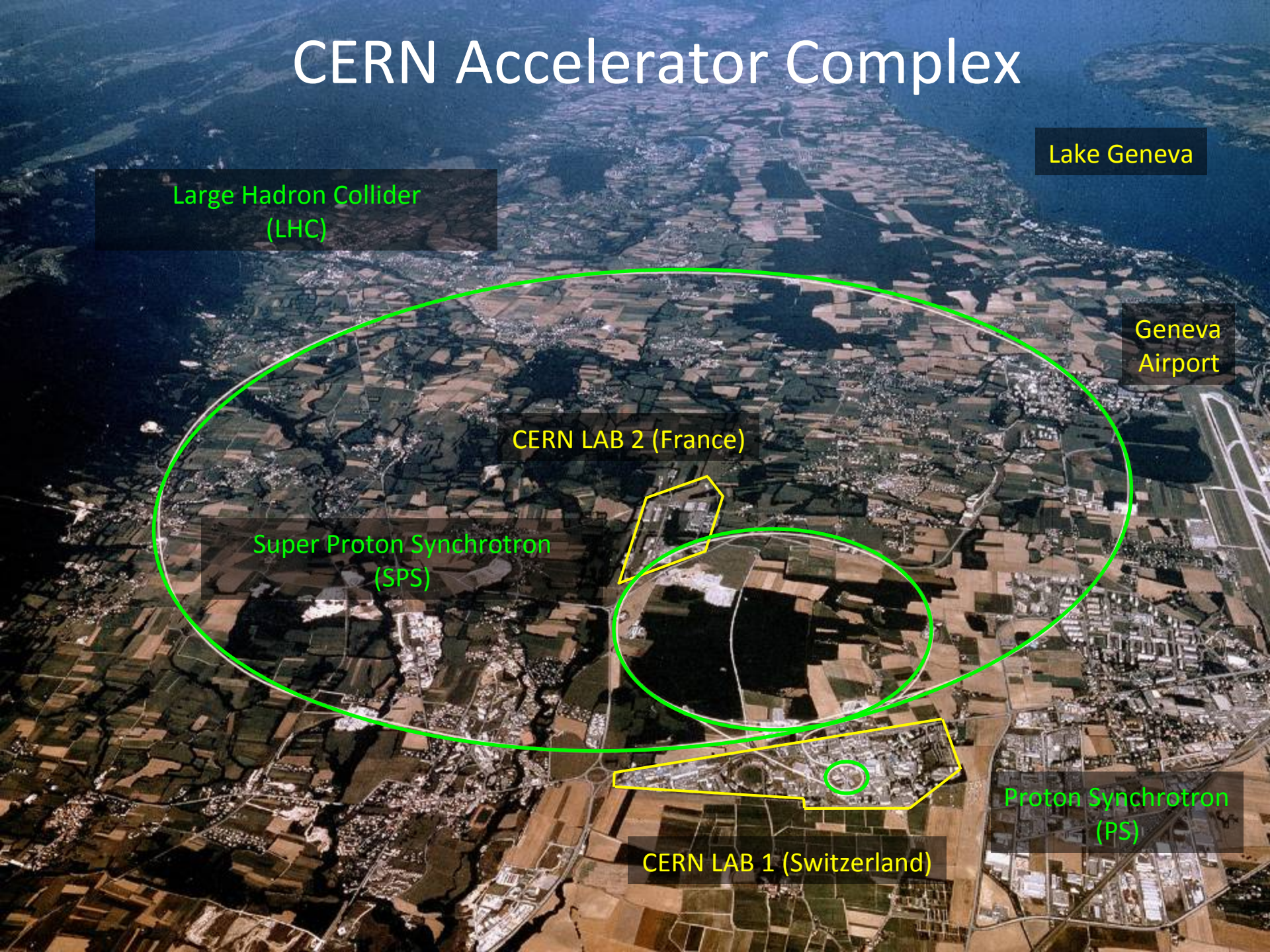
Geneva
Airport

CERN LAB 2 (France)

Super Proton Synchrotron
(SPS)

Proton Synchrotron
(PS)

CERN LAB 1 (Switzerland)



CERN Accelerator Complex

Large Hadron Collider
(LHC)

Beam Dumping Systems

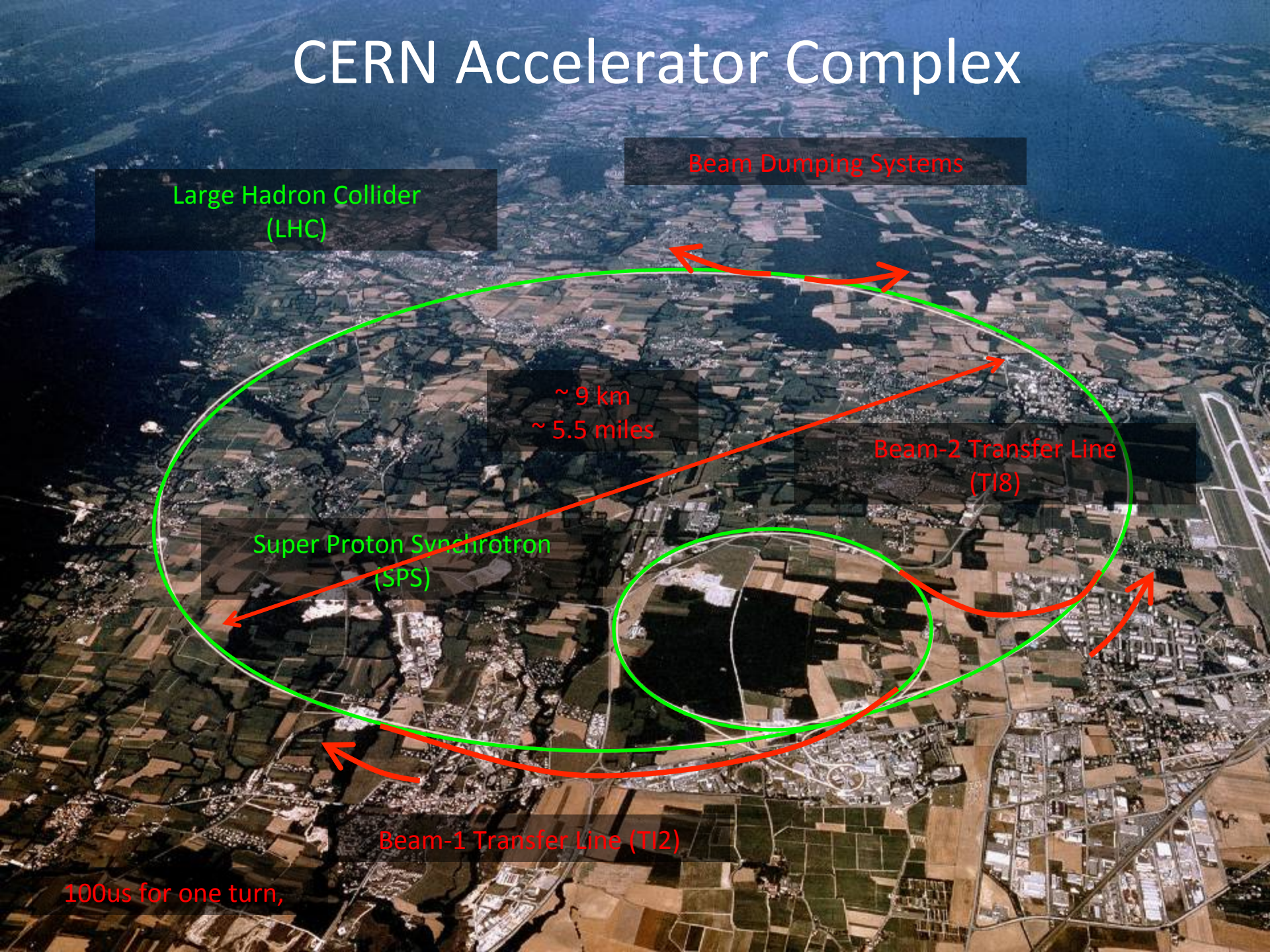
~ 9 km
~ 5.5 miles

Beam-2 Transfer Line
(T18)

Super Proton Synchrotron
(SPS)

Beam-1 Transfer Line (T12)

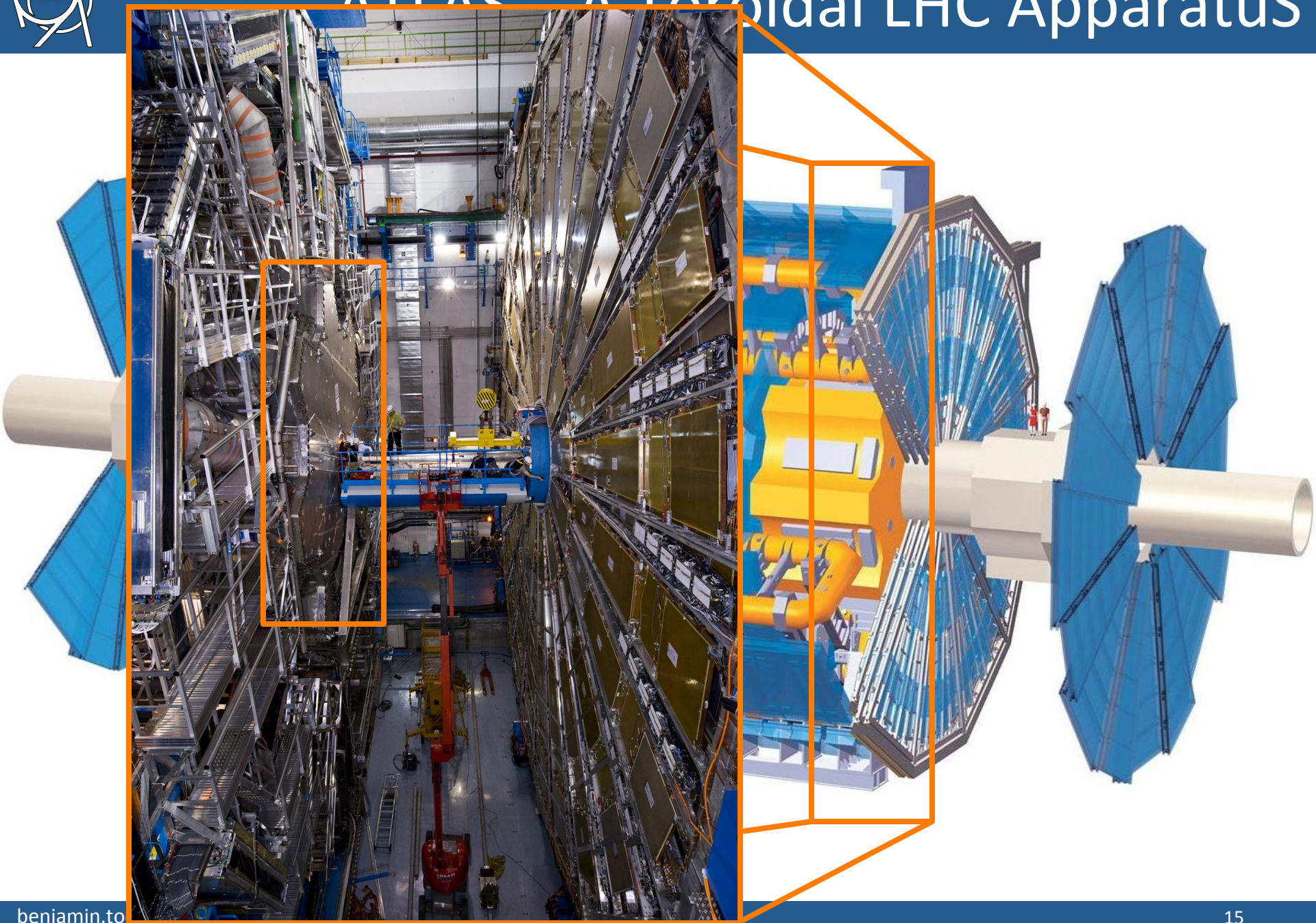
100us for one turn,

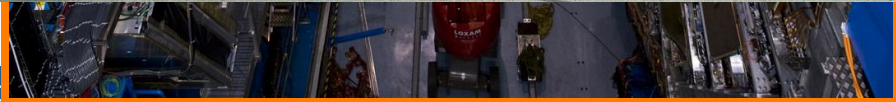
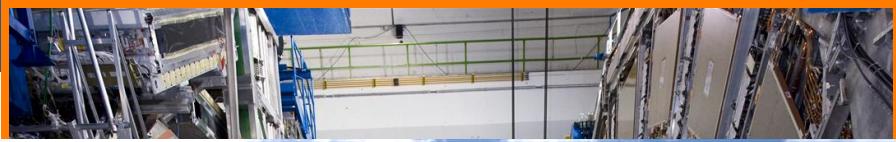


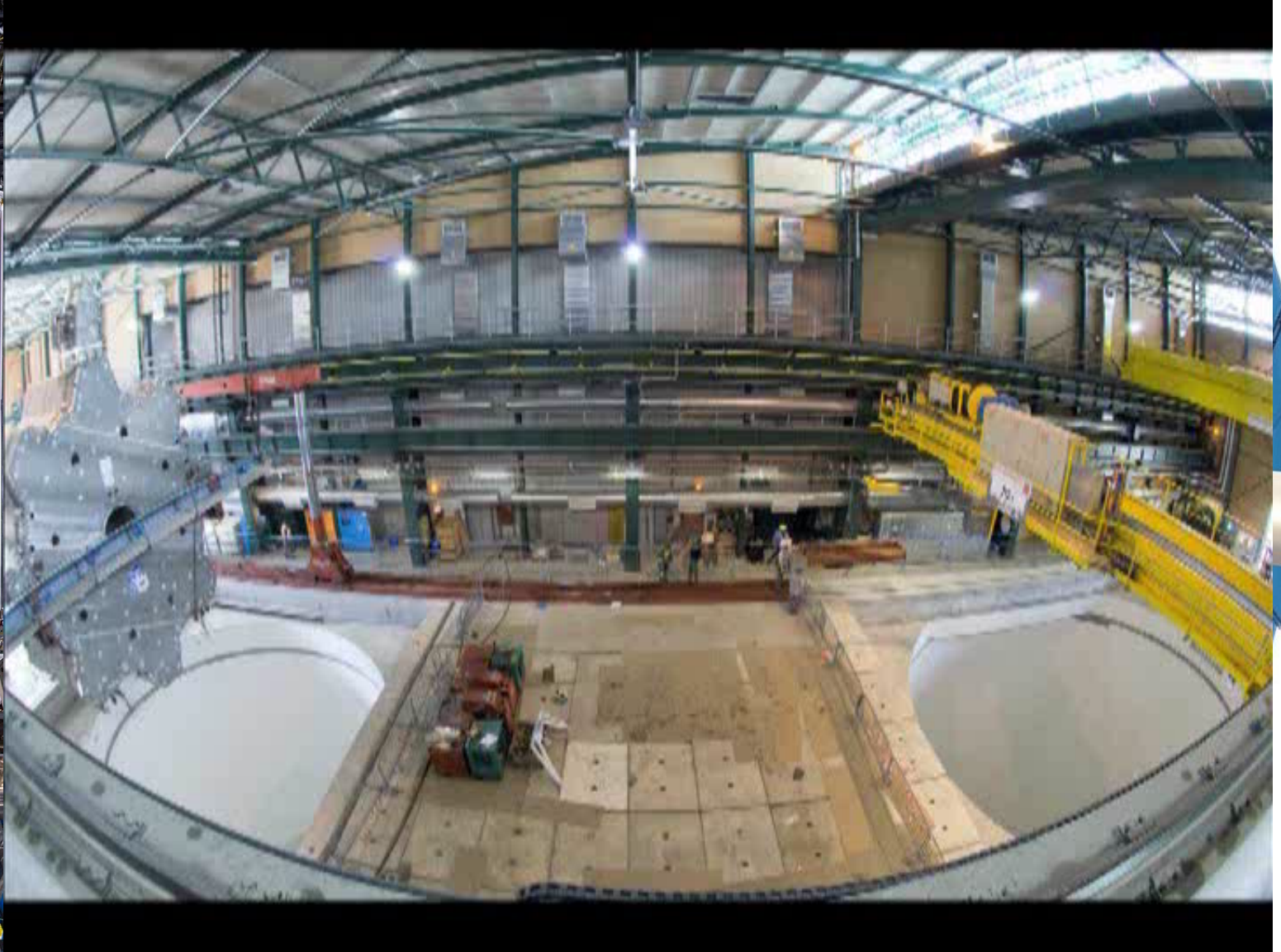
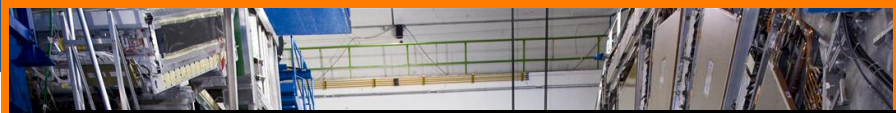
CERN Accelerator Complex



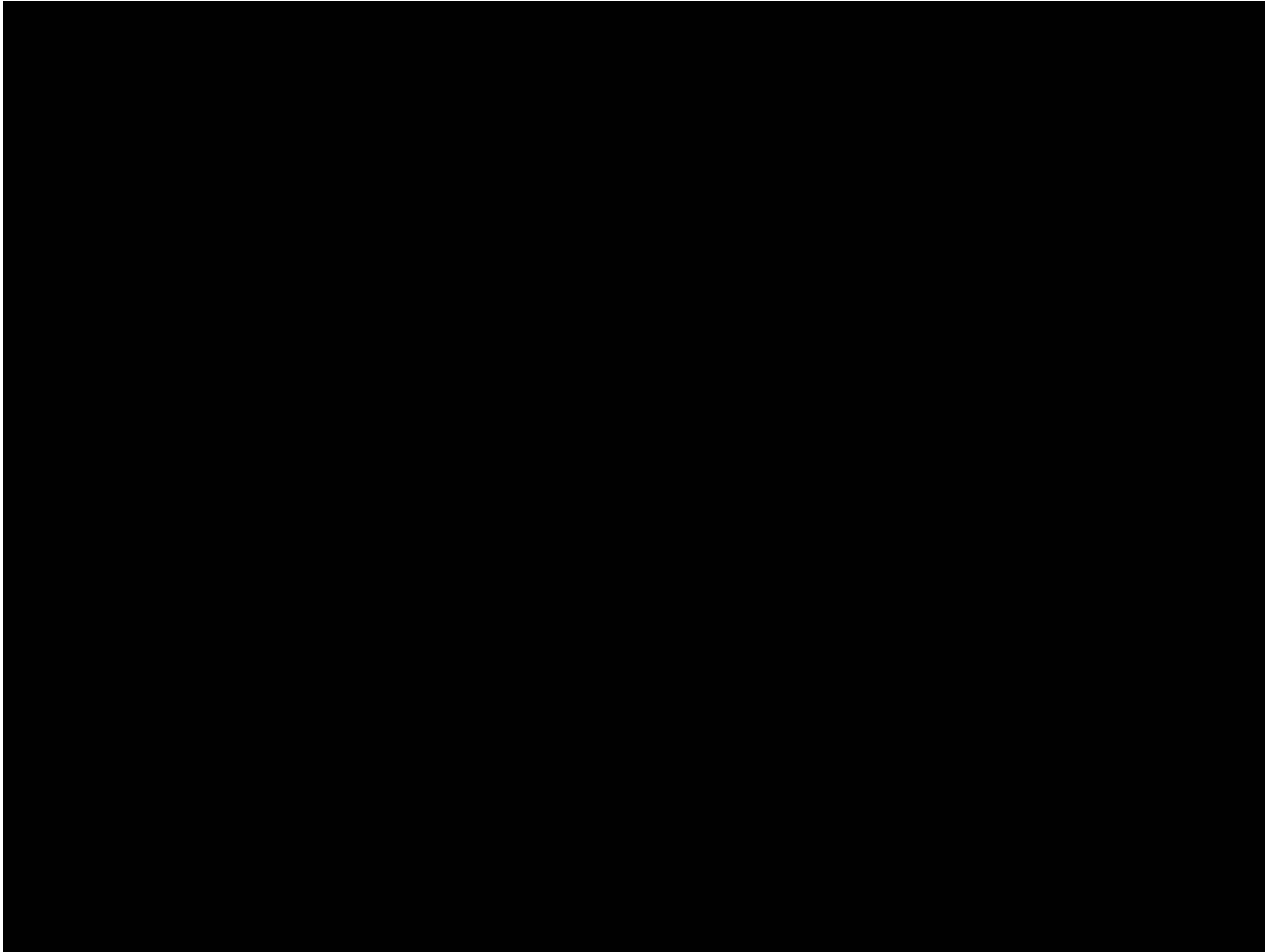
ATLAS A Toroidal LHC Apparatus







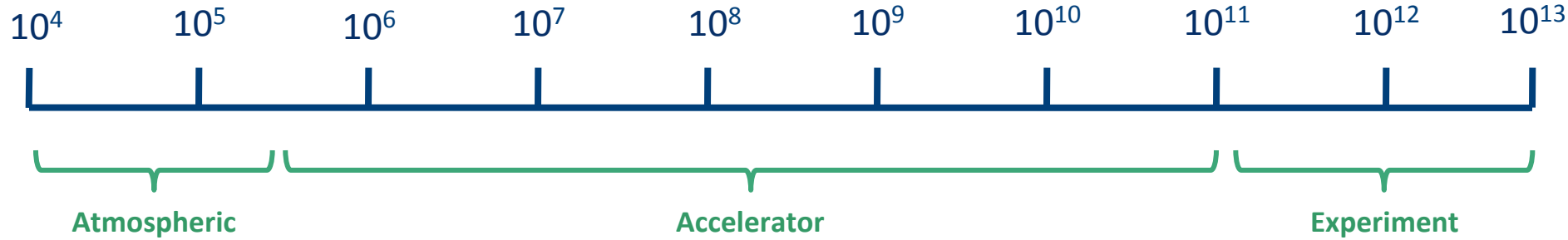
$\sim 10^9$ proton-proton collisions per second



Massive amounts of data generated – all must be processed
new particles are rare – only a few events per day

Radiation

[particles (HEH) per cm² per year]



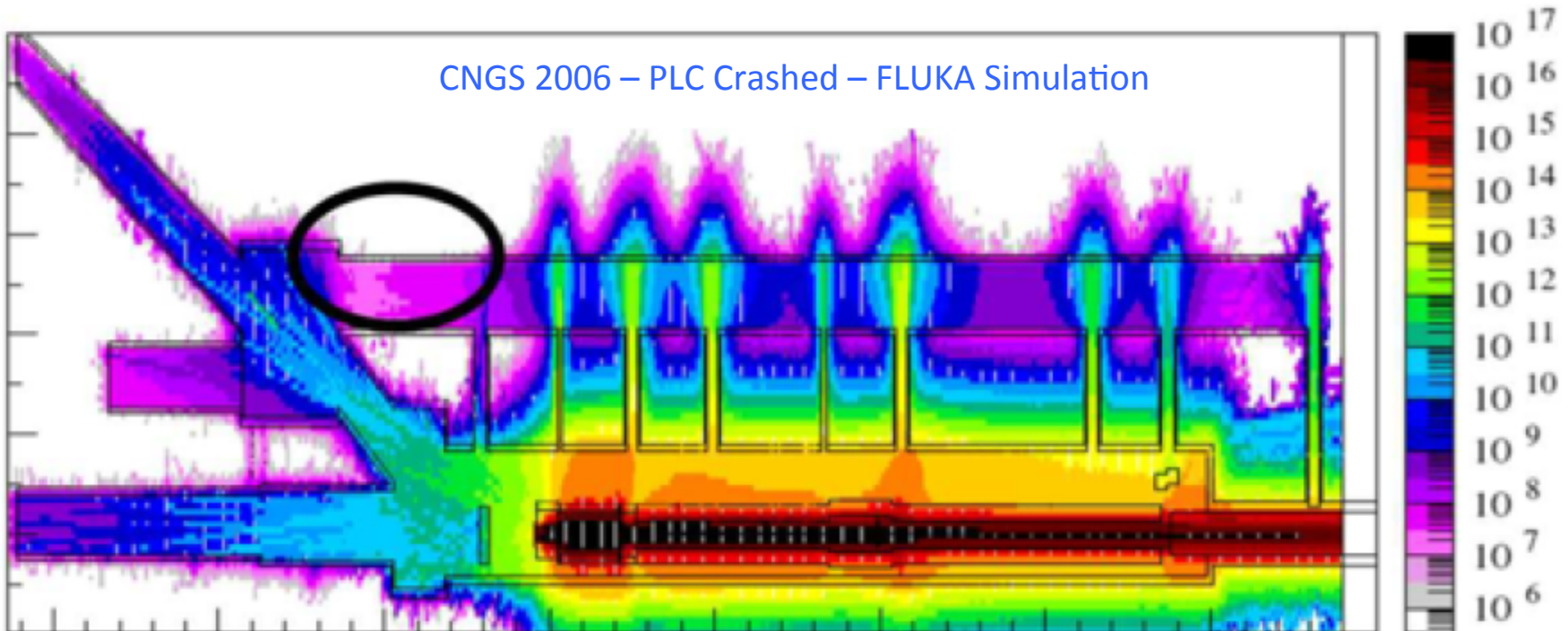
“Cross-Section” = the probability of a particle interacting

- If you have a lot of parts, even at sea level, atmospheric effects can noticeably affect reliability
 - Radiation effects cannot be ignored for highly reliable systems

If you only take one thing from this Saturday morning talk – let it be this:

To solve radiation issues:

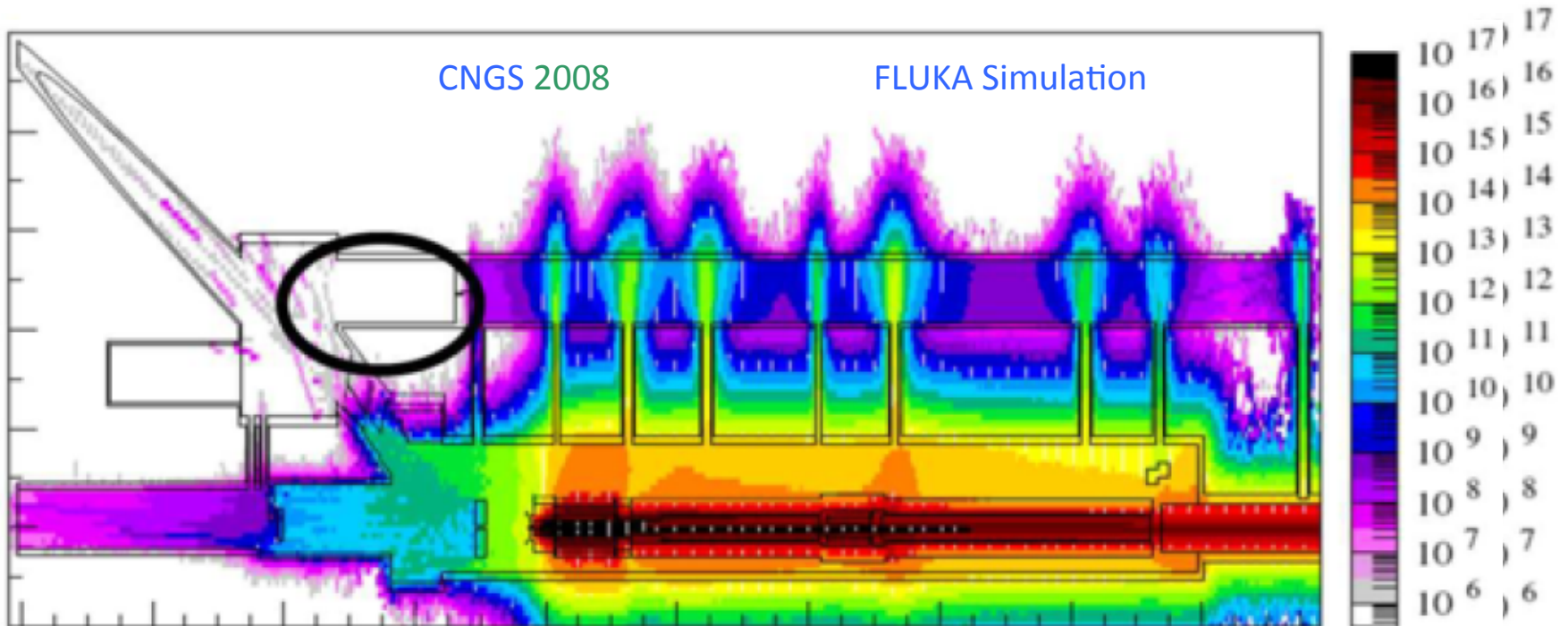
- 1) **Remove** the function if not possible then
- 2) **Move** away from the radiation if not possible then
- 3) **Block** radiation if not possible then
- 4) and only then - **conceive** a radiation tolerant system



If you only take one thing from this Saturday morning talk – let it be these golden rules:

To solve radiation issues:

- 1) **Remove** the function if not possible then
- 2) **Move** away from the radiation if not possible then
- 3) **Block** radiation if not possible then
- 4) and only then - **conceive** a radiation tolerant system



1. Displacement Damage (DD)

2. Total Ionising Dose (TID)

3. Single Event Effects (SEE)



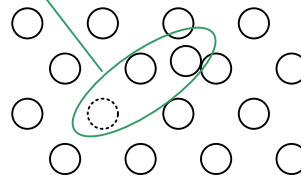
prompt

1. Displacement Damage (DD)

2. Total Ionising Dose (TID)

3. Single Event Effects (SEE)

Frenkel Defect

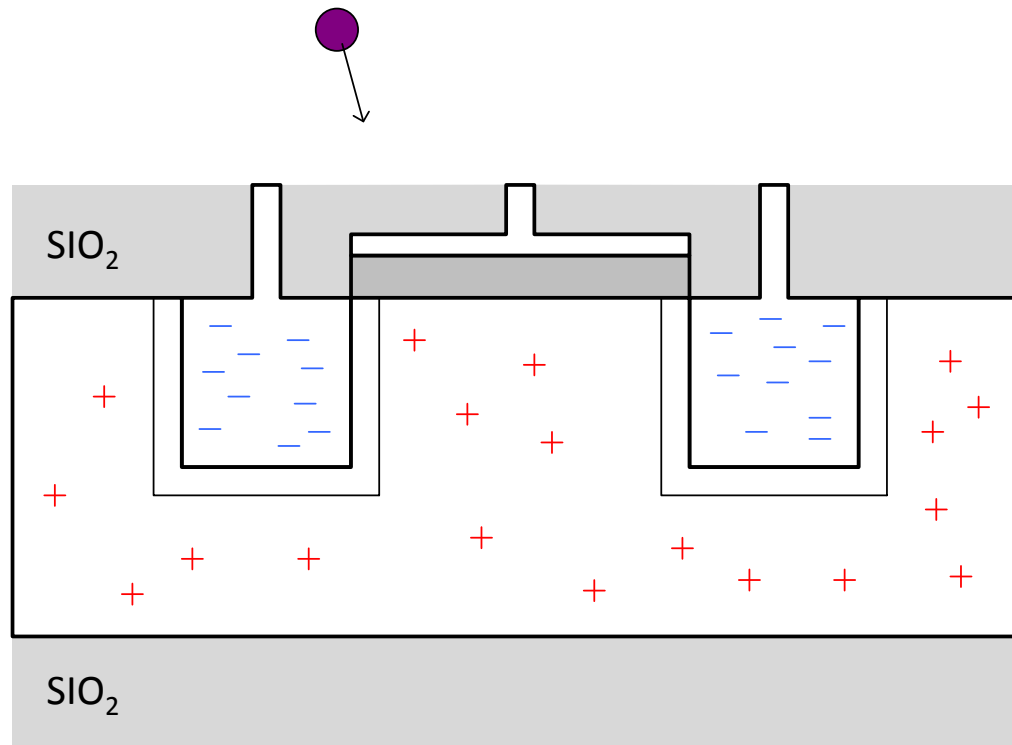


defects accumulate and gradually destroy the silicon lattice

1. Displacement Damage (DD)

2. Total Ionising Dose (TID)

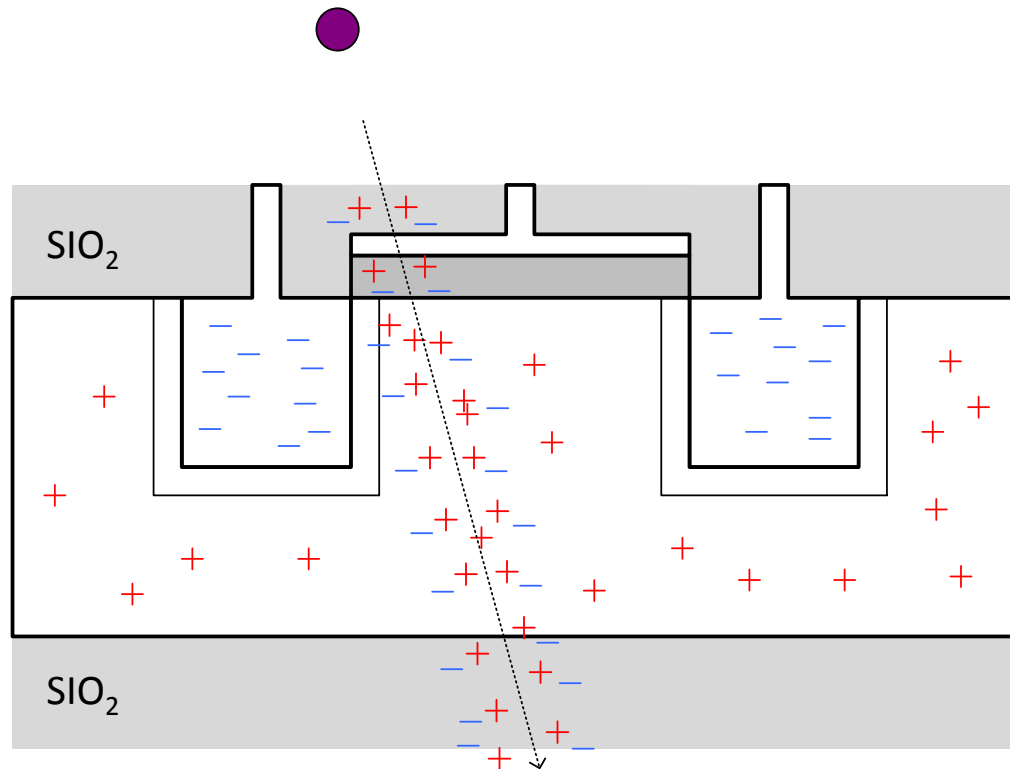
3. Single Event Effects (SEE)



1. Displacement Damage (DD)

2. Total Ionising Dose (TID)

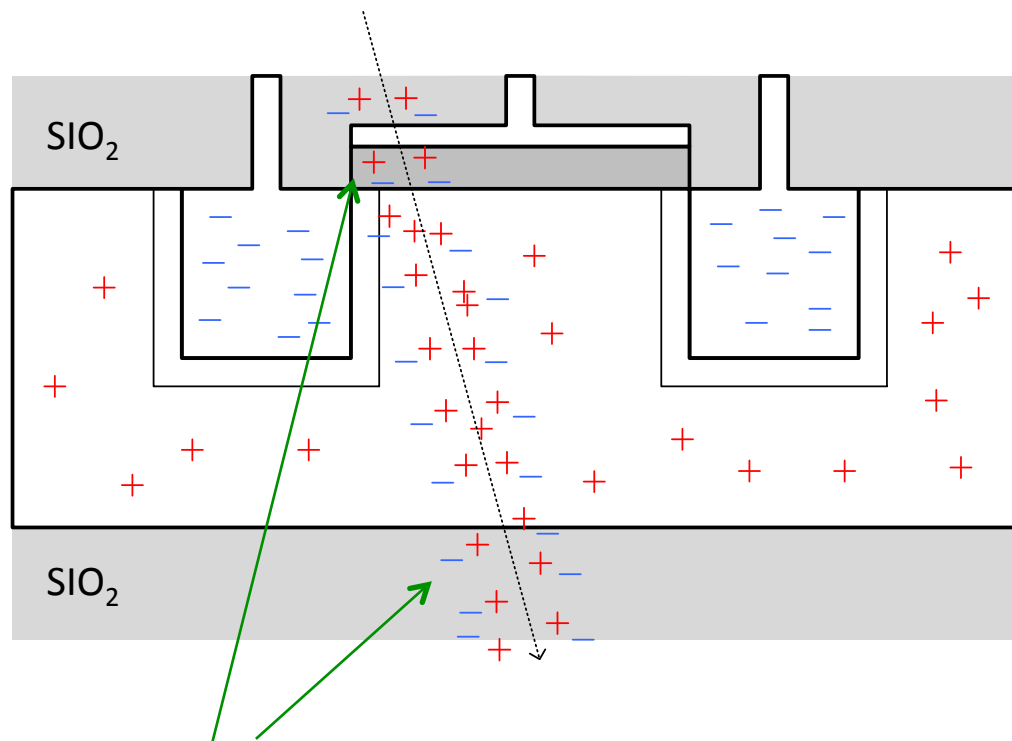
3. Single Event Effects (SEE)



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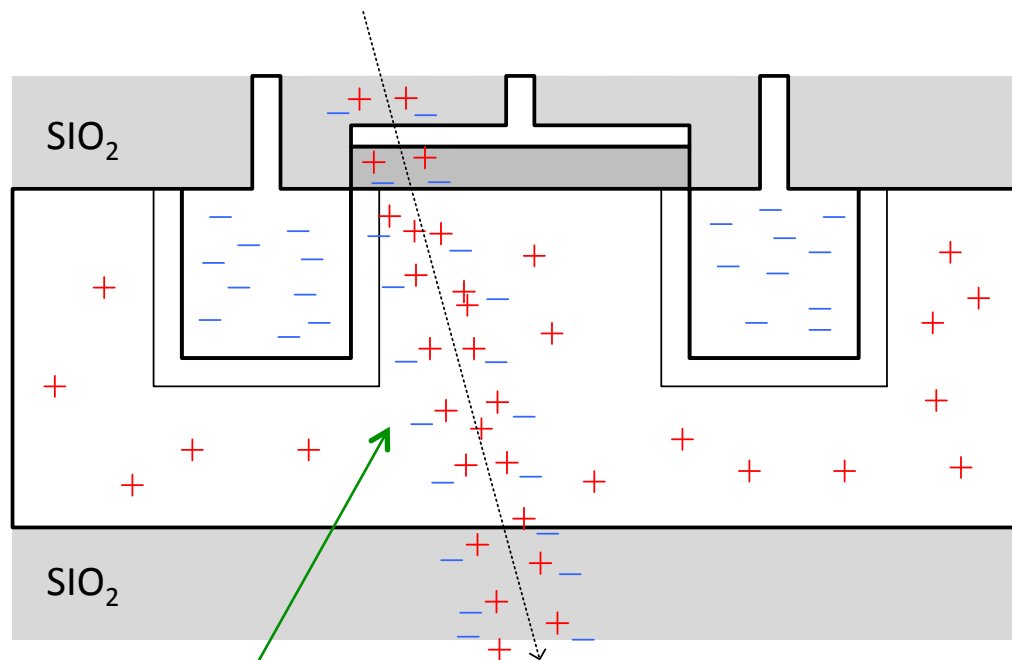


accumulate and gradually degrade the transistor function

1. Displacement Damage (DD)

2. Total Ionising Dose (TID)

3. Single Event Effects (SEE)



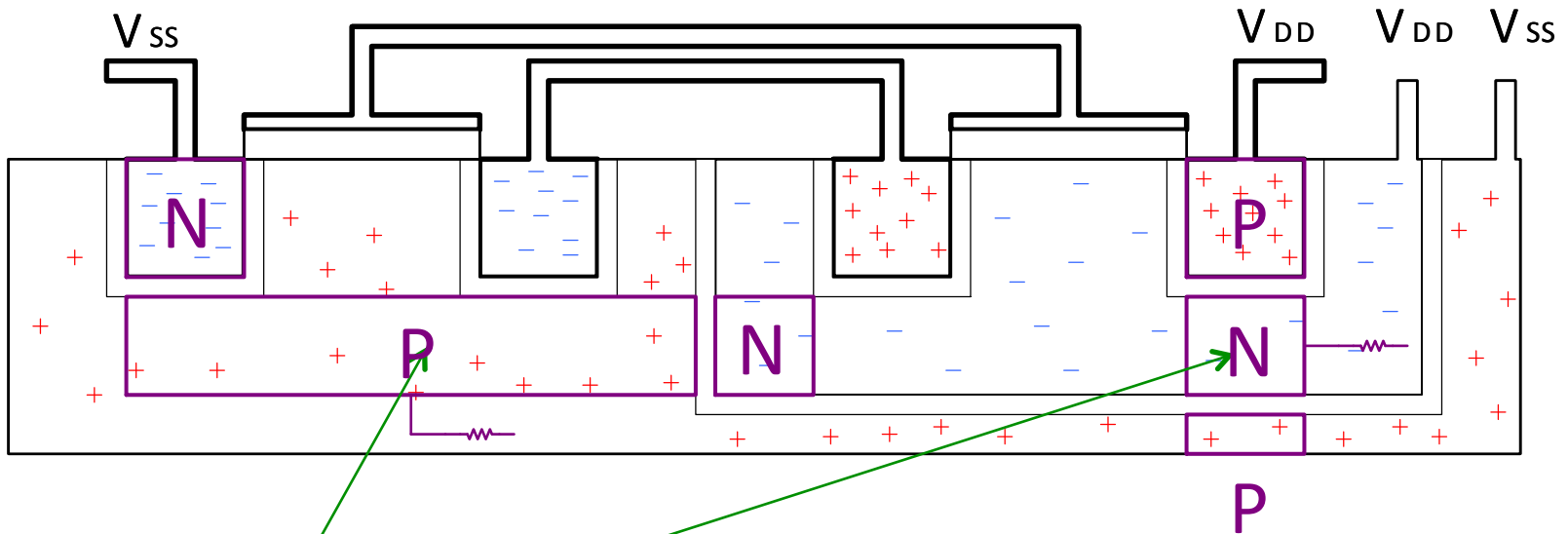
electrons collected by junctions creating parasitic current

SE Transient (SET) → SE Upset (SEU)
 ↘ SE Functional Interrupt (SEFI)

1. Displacement Damage (DD)

2. Total Ionising Dose (TID)

3. Single Event Effects (SEE)



CMOS parasitic bi-polar transistors...
Switch on = short drain to source...

SE Latch-up (SEL)

1. Displacement Damage (DD)

cumulative

Non-Ionising Energy Loss

2. Total Ionising Dose (TID)

cumulative

Grays

3. Single Event Effects (SEE)

prompt

Cross-section

SE Upset (SEU)

SE Transient (SET)

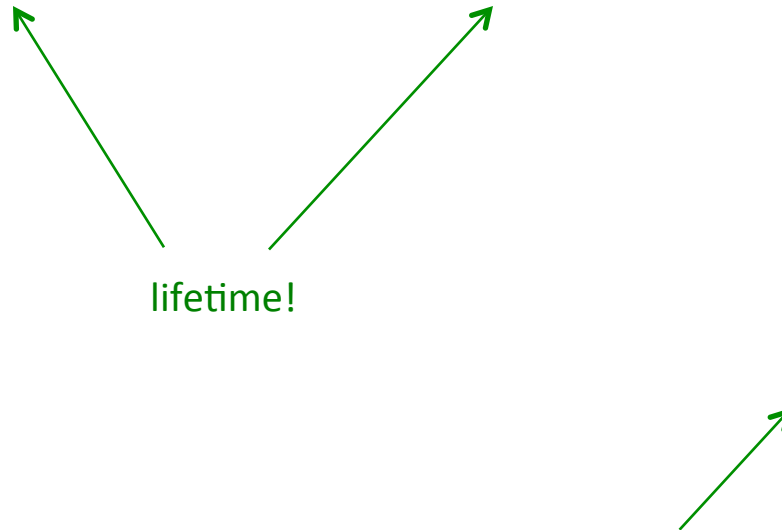
SE Functional Interrupt (SEFI)

SE Latchup (SEL)

SE Burnout (SEB)

lifetime!

random in time failure!

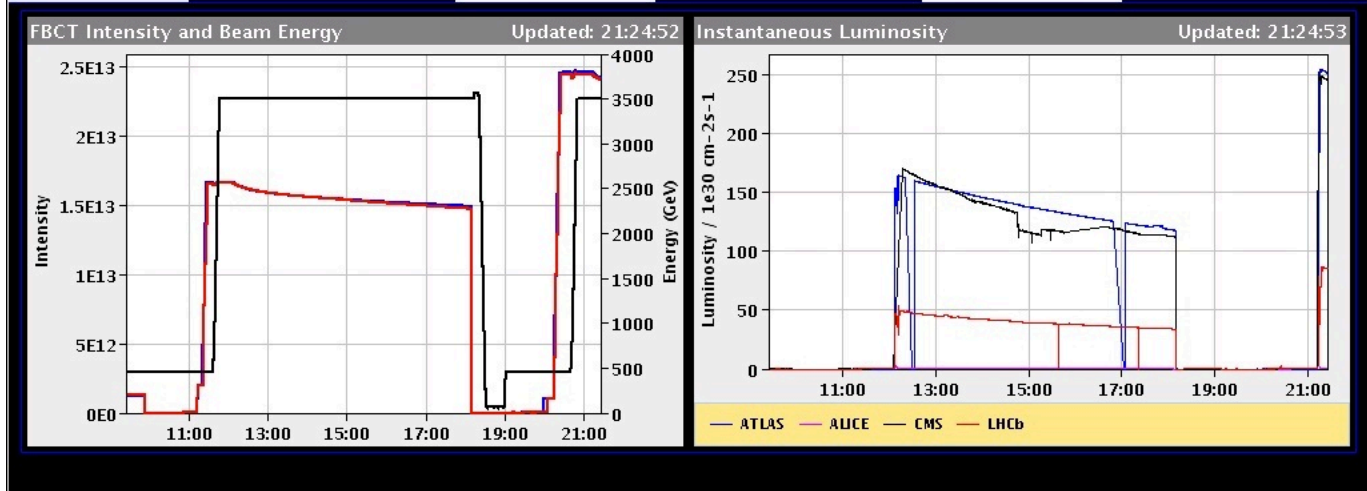


A System In Design Today

LHC Page1 Fill: 1645 E: 3500 GeV 22-03-2011 21:24:54

PROTON PHYSICS: STABLE BEAMS

Energy: 3500 GeV I(B1): 2.43e+13 I(B2): 2.41e+13



Comments 22-03-2011 21:21:07 :
STABLE BEAMS

BIS status and SMP flags	B1	B2
Link Status of Beam Permits	true	true
Global Beam Permit	true	true
Setup Beam	false	false
Beam Presence	true	true
Moveable Devices Allowed In	true	true
Stable Beams	true	true

AFS: 75ns_200b_194_178_188_24bpi9inj PM Status B1 ENABLED PM Status B2 ENABLED

Power Converters = Power Supplies

Critical for operation of CERN's machines

Direct impact on beam quality

Direct impact on machine availability

Year	Peak Energy [TeV]	Peak Intensity [p]	Peak Luminosity [cm ⁻² s ⁻¹]
2010	3.5	4×10^{13}	2.0×10^{32}
2011	3.5	2.0×10^{14}	3.6×10^{33}
2012	4	2.2×10^{14}	7.7×10^{33}
LS ₁₋₂	≈6.5	≈ 3×10^{14}	≈ 1×10^{34}

[2,3,4]

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<u>LS₁₋₂</u>	≈6.5	≈ 3×10^{14}	≈ 1×10^{34}

[2,3,4]

LS1 = Long Shutdown #1 – from 2013 to 2014 – upgrade magnet interconnects
 LS2 = Long Shutdown #2 ...

Power Converters = Power Supplies

Critical for operation of CERN's machines

Direct impact on beam quality

Direct impact on machine availability

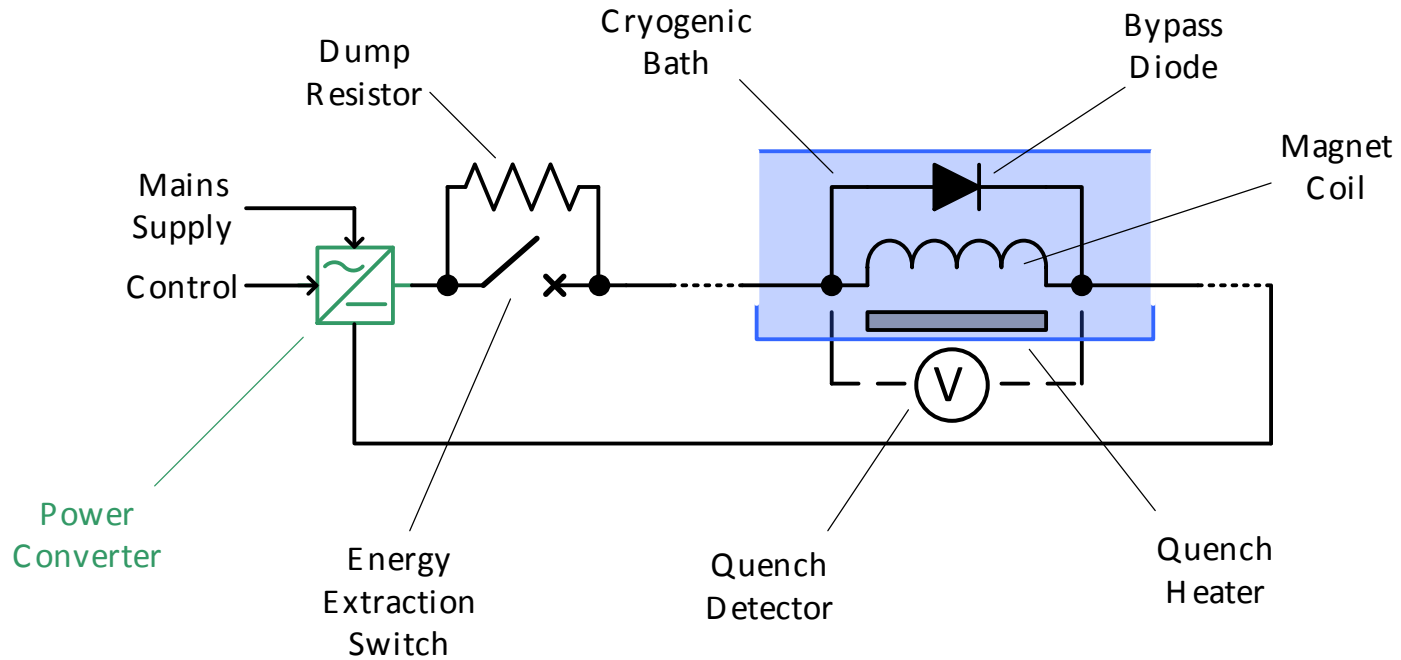
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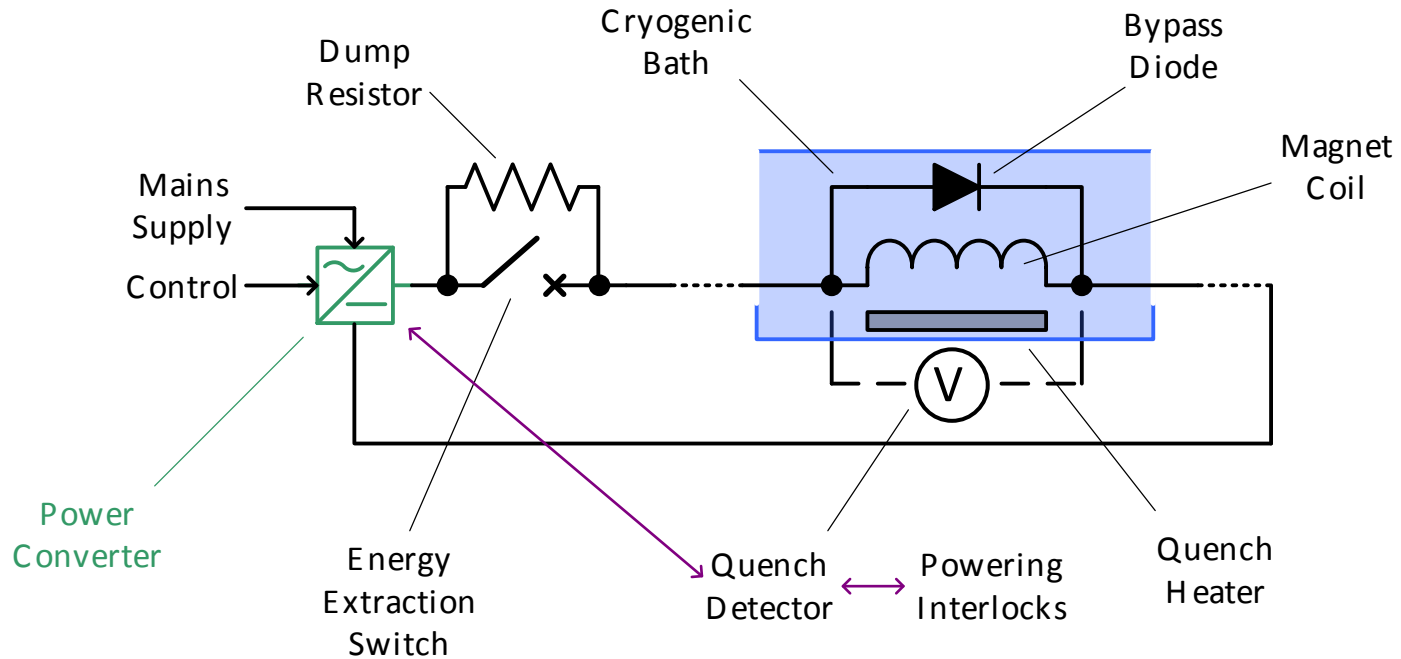
Increasing energy and intensity = increasing levels of radiation in machine environment [2,3,4]

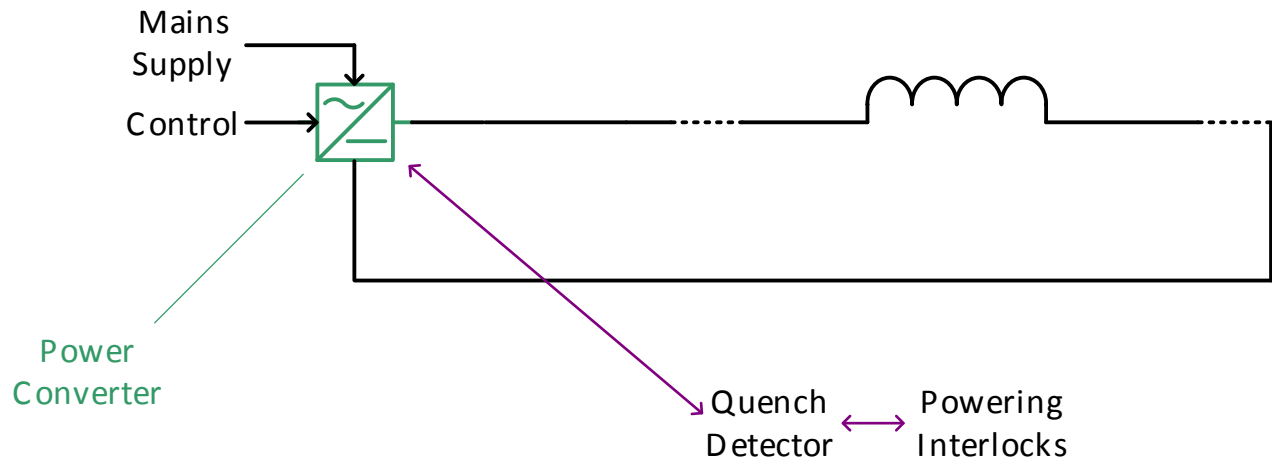
existing converter controls would have low availability when higher energies and intensities are reached in the LS₁₋₂ era

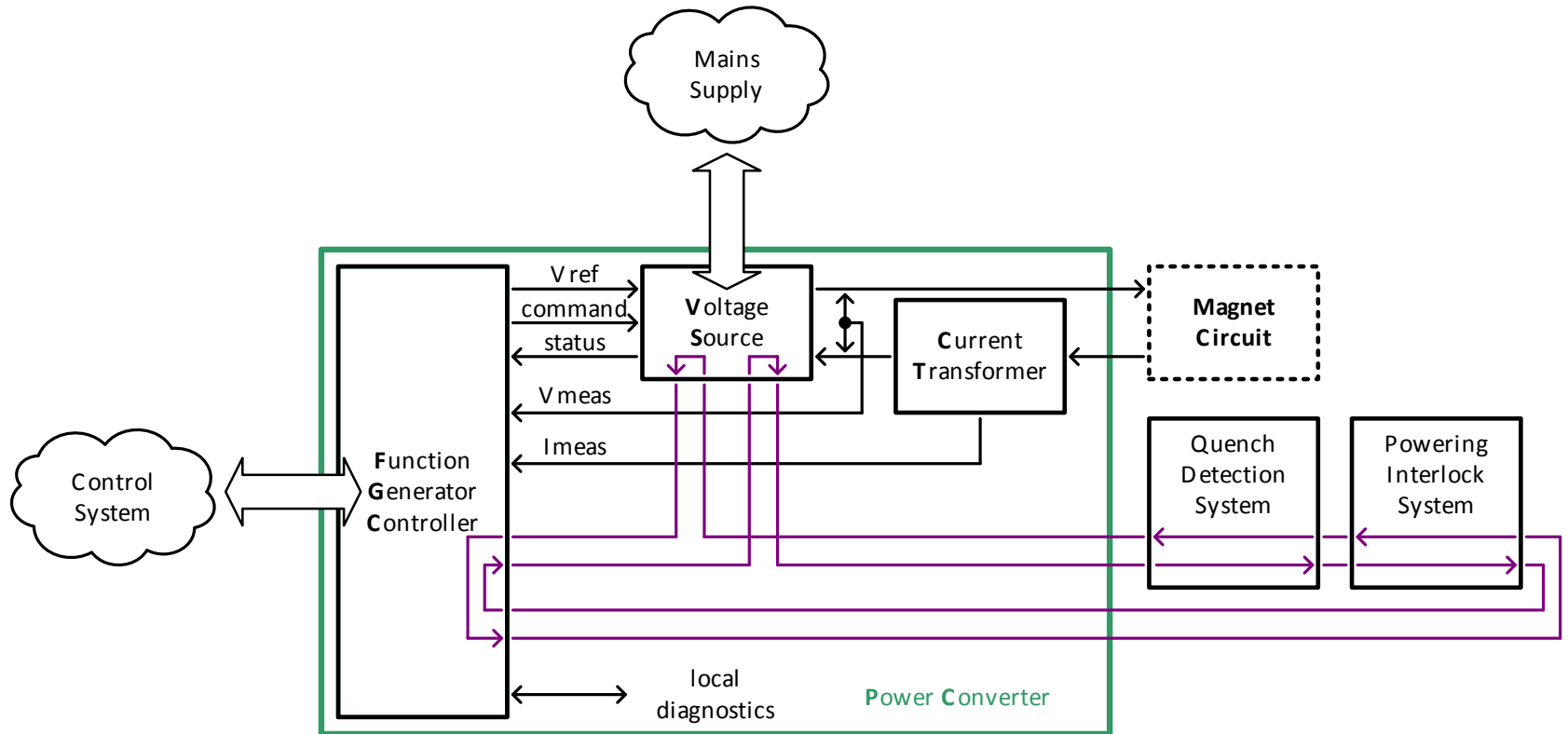
Function Generator Controller \longrightarrow Function Generator Controller lite

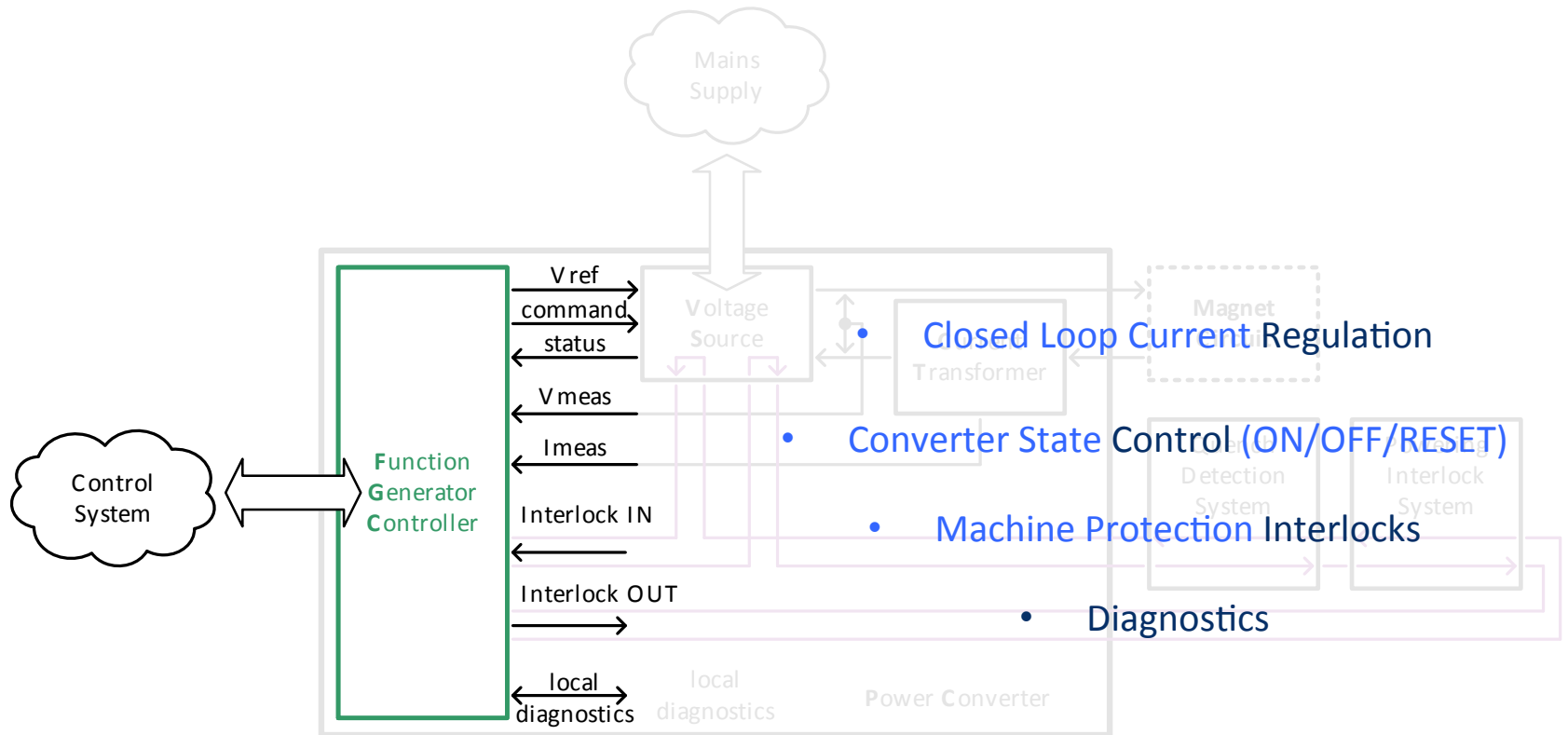
a design optimised for high availability in radiation = the next 25 years of LHC



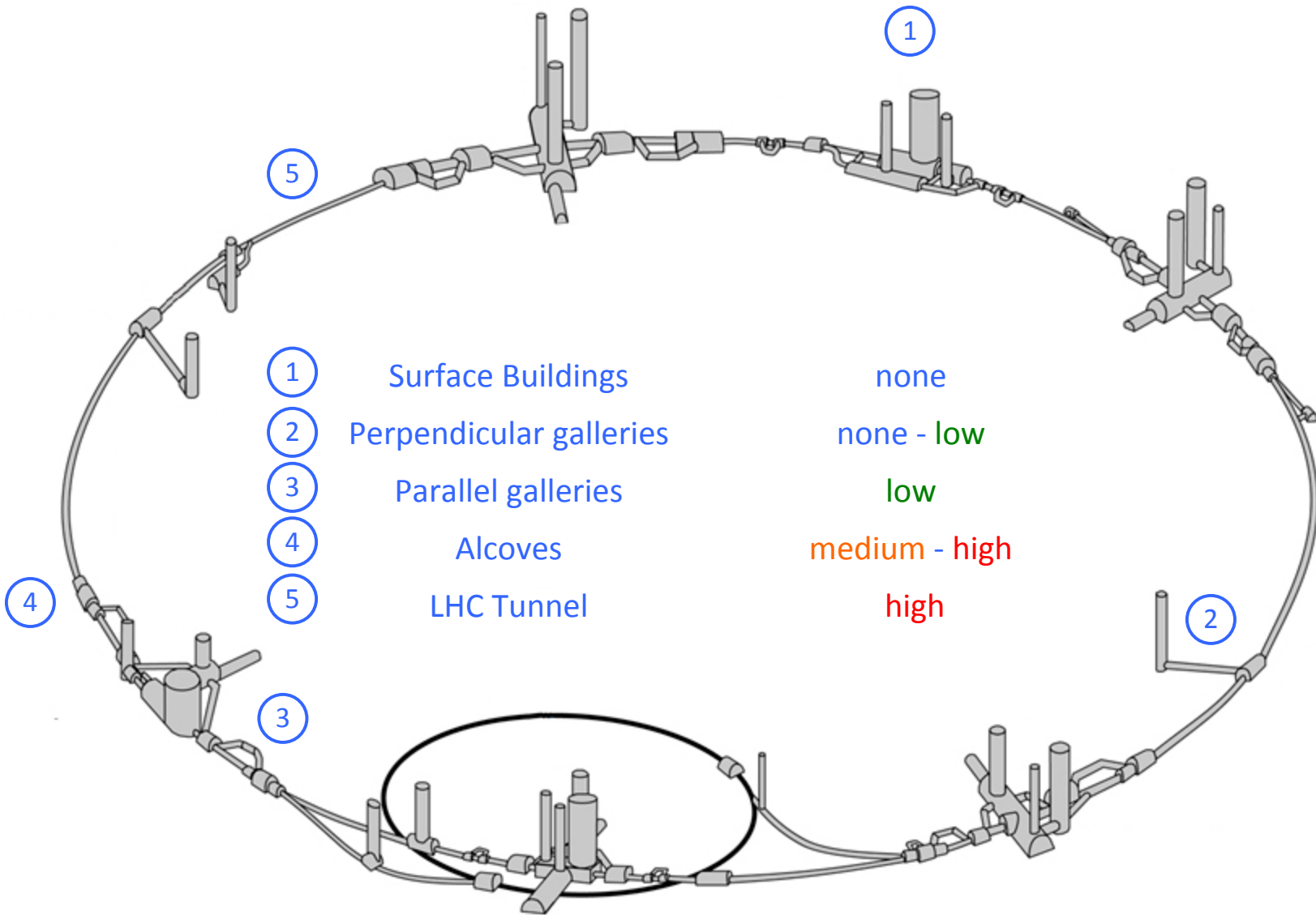




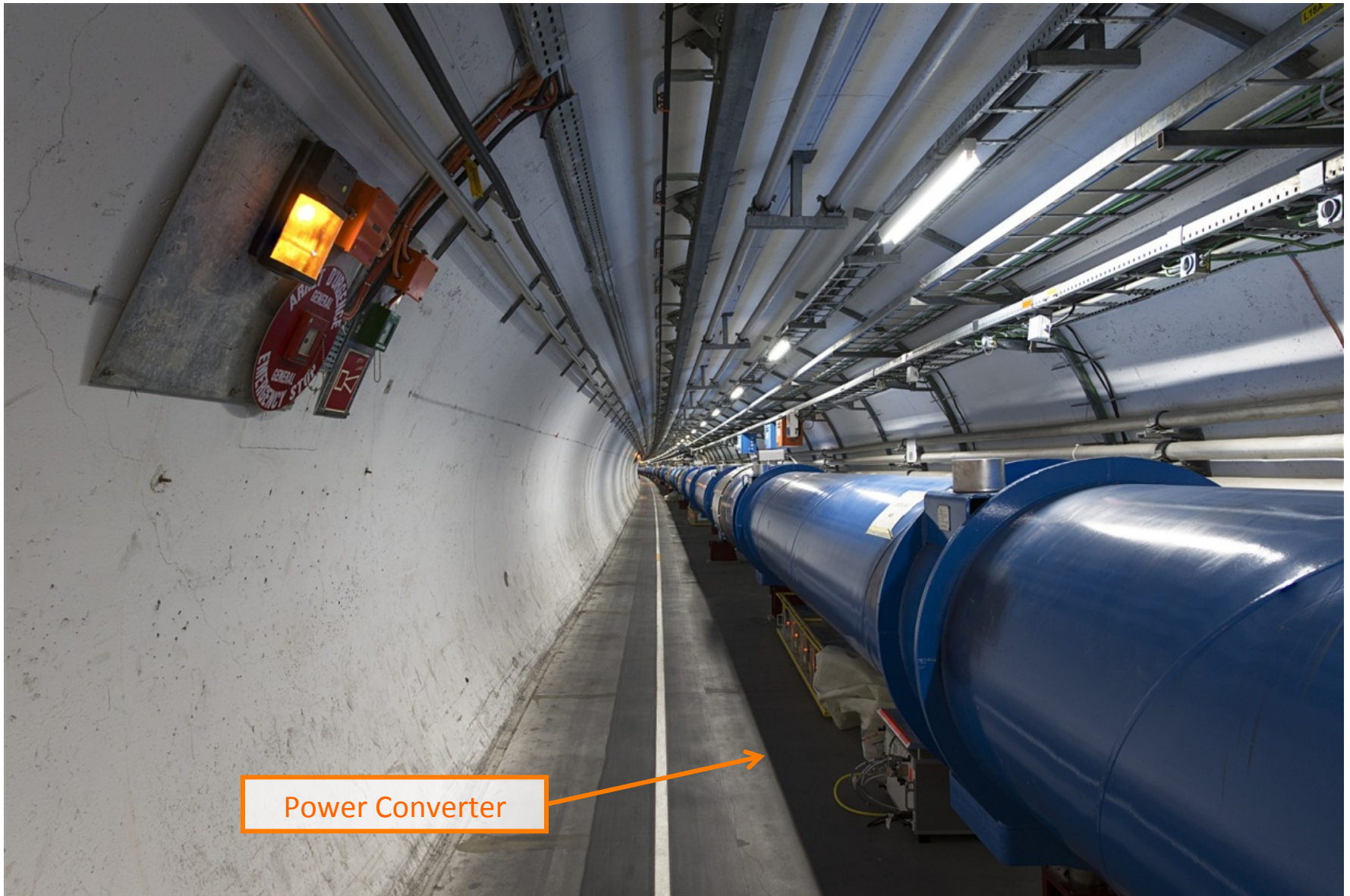




Power converters are installed in one of five areas with machine radiation risks:



Power converters are installed in one of five areas with machine radiation risks:



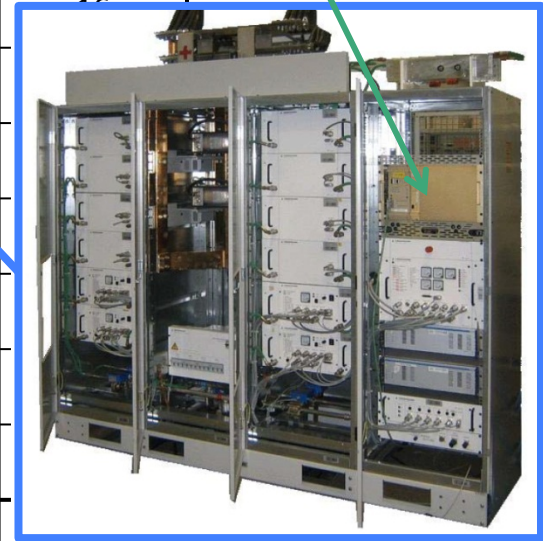
Power Converter

Converter Requirements			Quantity
Typical Use	Current	Voltage	
Main Dipoles	13000	190	8
Main Quadrupoles	13000	18	16
Quadrupole Circuits	4-6-8000	8	189
Warm Circuits	1000	450-950	16
Sextupole Circuits	600	40	37
Octupole Circuits	600	10	400
Orbit Correctors	120	10	290
Orbit Correctors	60	8	752
Total			>1700



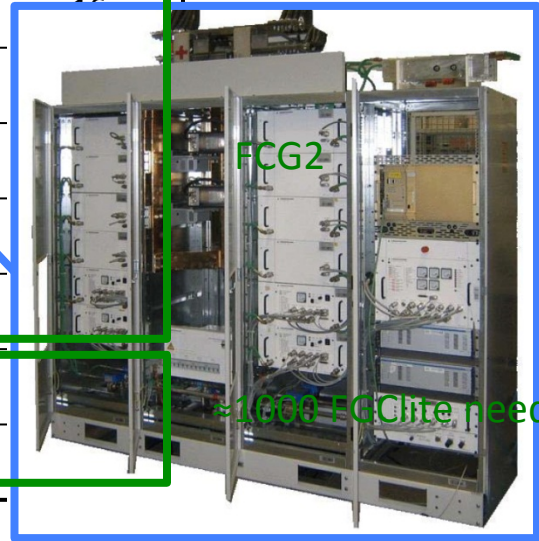
Function Generator Controller

Requirements	Current	Voltage	Quantity
	13000	190	8
	13000	18	
	4-6-8000	8	
	1000	450-950	
Sextupole Circuits	600	40	
Octupole Circuits	600	10	
ectors	120	10	
ectors	60	8	
Total			2700





	Requirements		Quantity
	Current	Voltage	
	13000	190	8
	13000	18	
	4-6-8000	8	
	1000	450-950	
Sextupole Circuits	600	40	
Octupole Circuits	600	10	
ectors	120	10	
ectors	60	8	
Total			1700

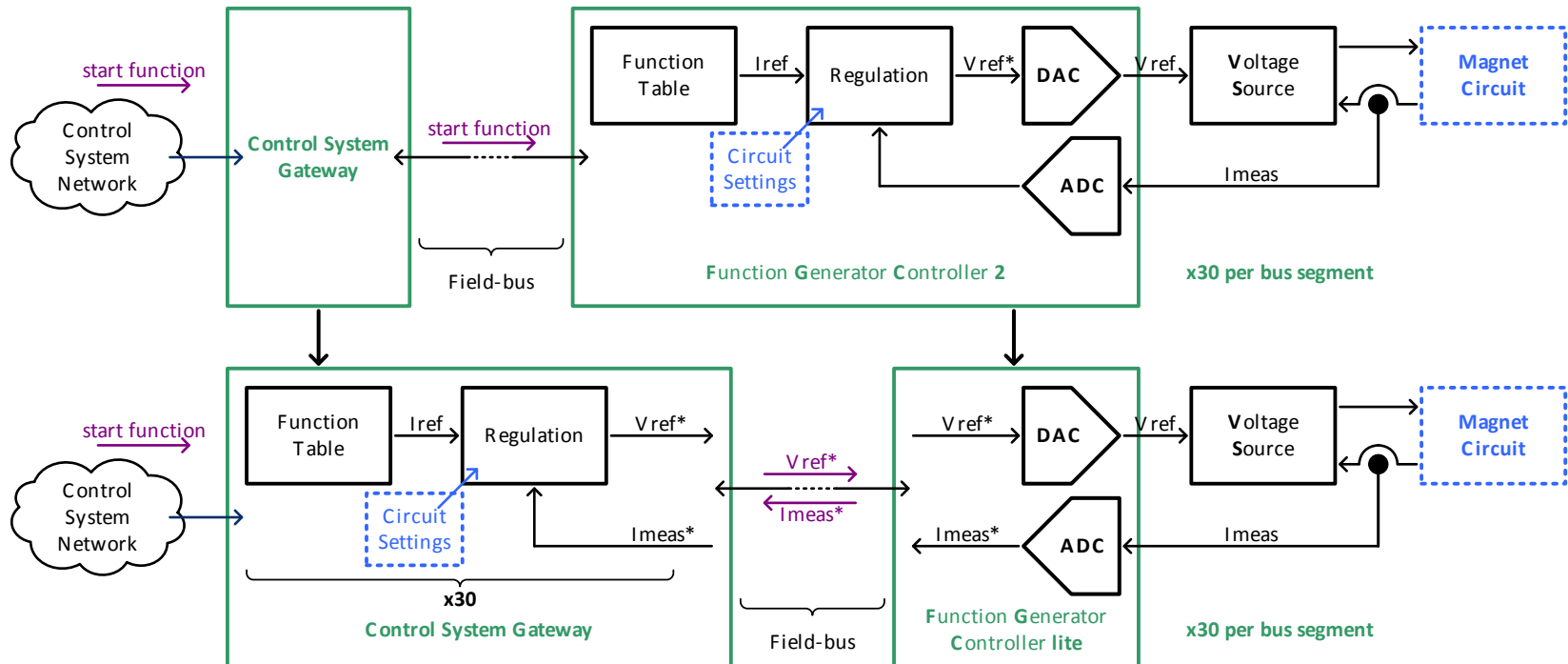


FCG2

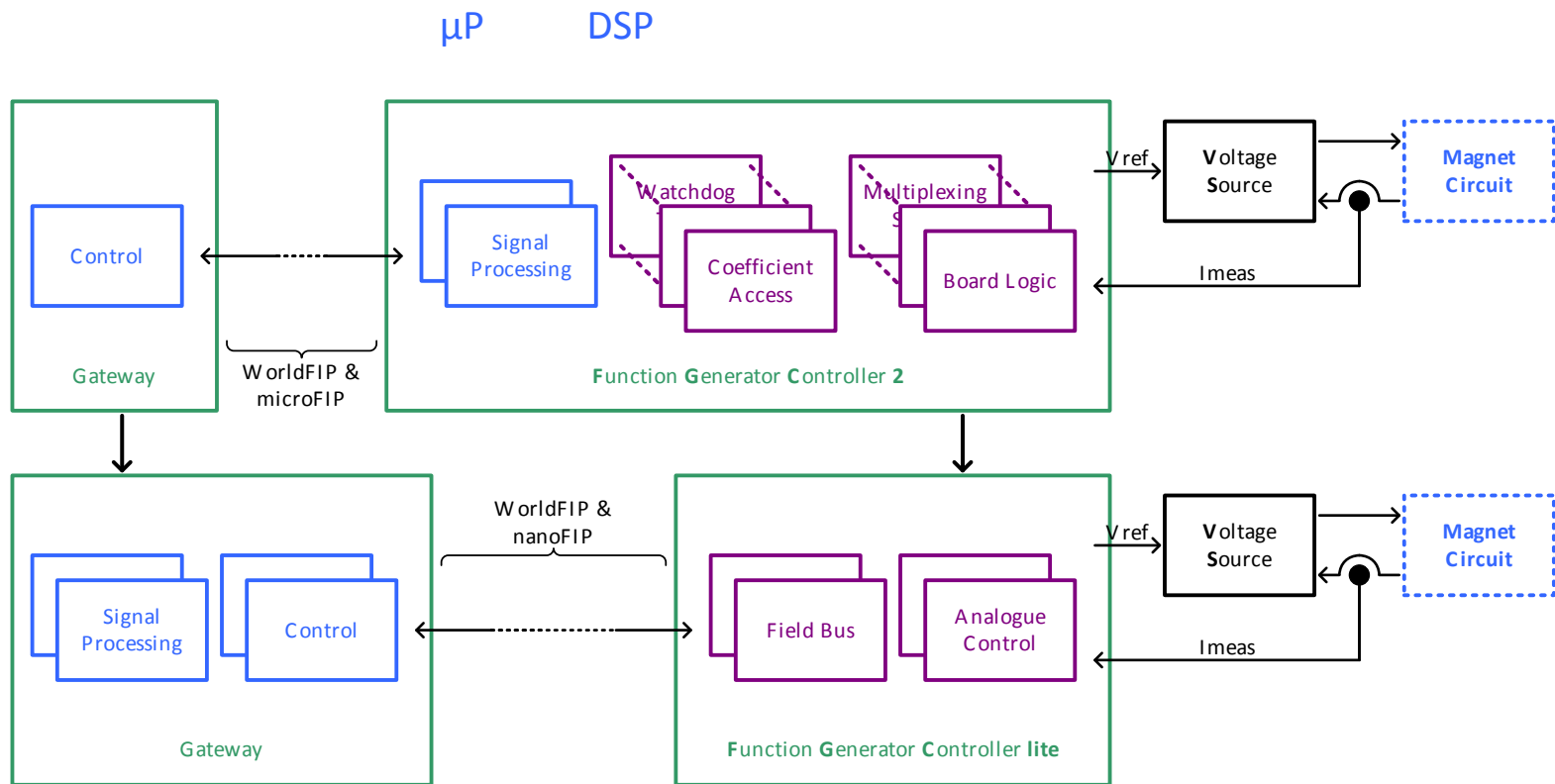
≈1000 FCGlite needed...

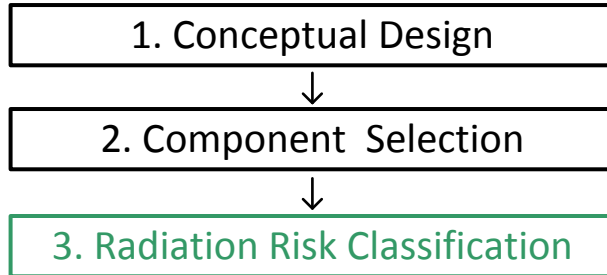


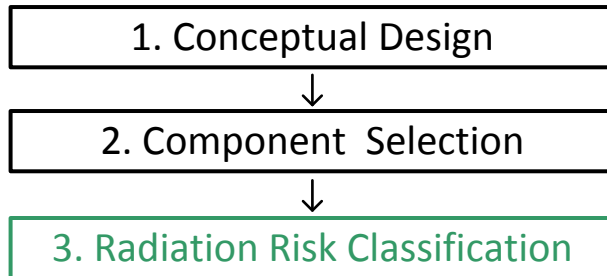




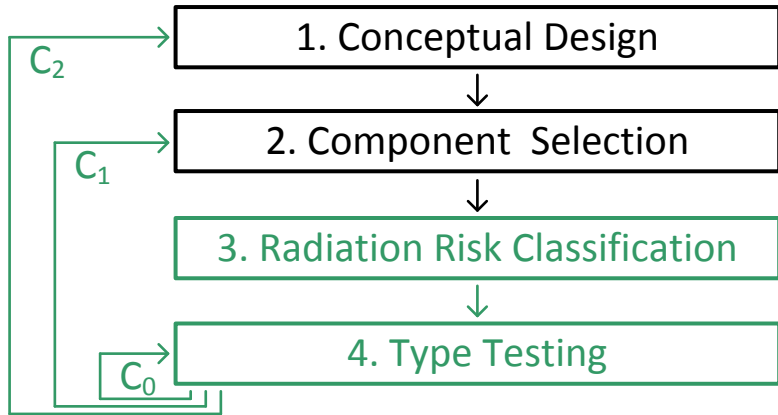
Software versus Programmable Logic



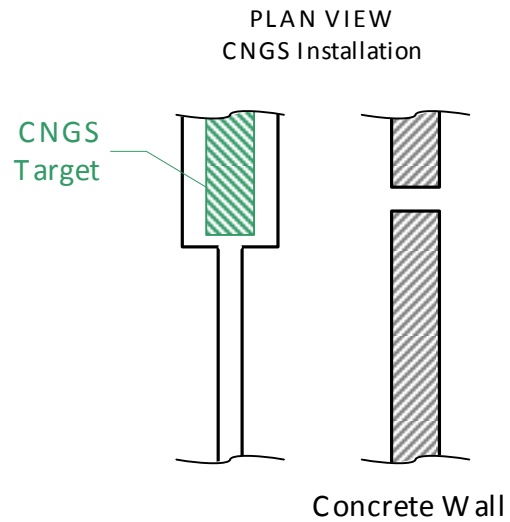




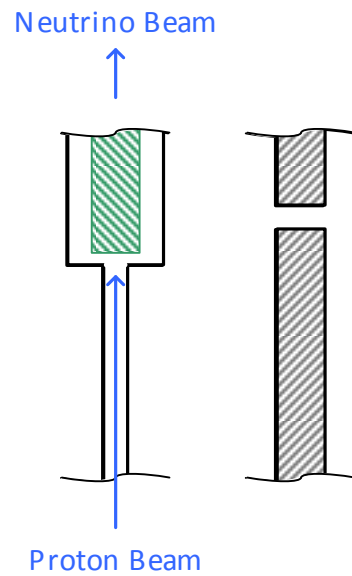
- Class 0 (C_0) components known to be resistant, or easily replaced, conceptual design not influenced by these components.
Resistors, capacitors, diodes, transistors...
- Class 1 (C_1) components potentially susceptible to radiation, in less-critical parts of the system. Substitution of parts or mitigation of issues is possible with a re-design.
Regulators, memory, level translators...
- Class 2 (C_2) components potentially susceptible to radiation, in more-critical parts of the system. The conceptual design is compromised if these components do not perform well. Substitution of parts or mitigation of issues would be difficult.
ADC, FPGA, fieldbus driver



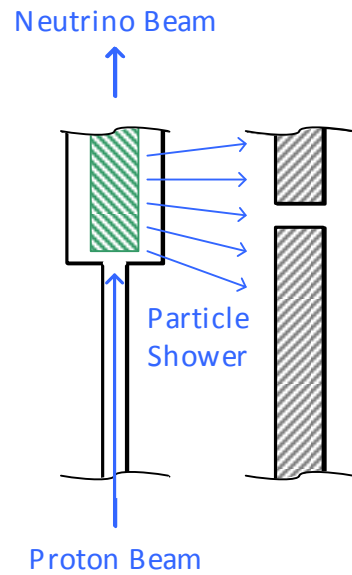
Principle for Test-bench “CIRX”



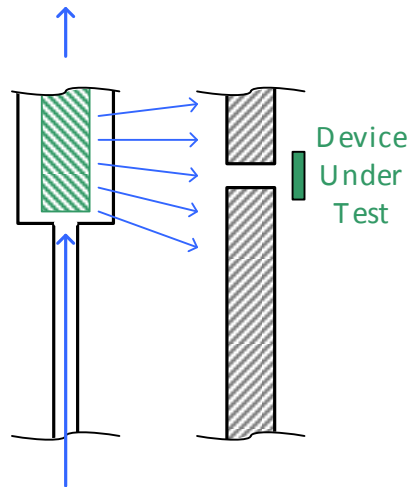
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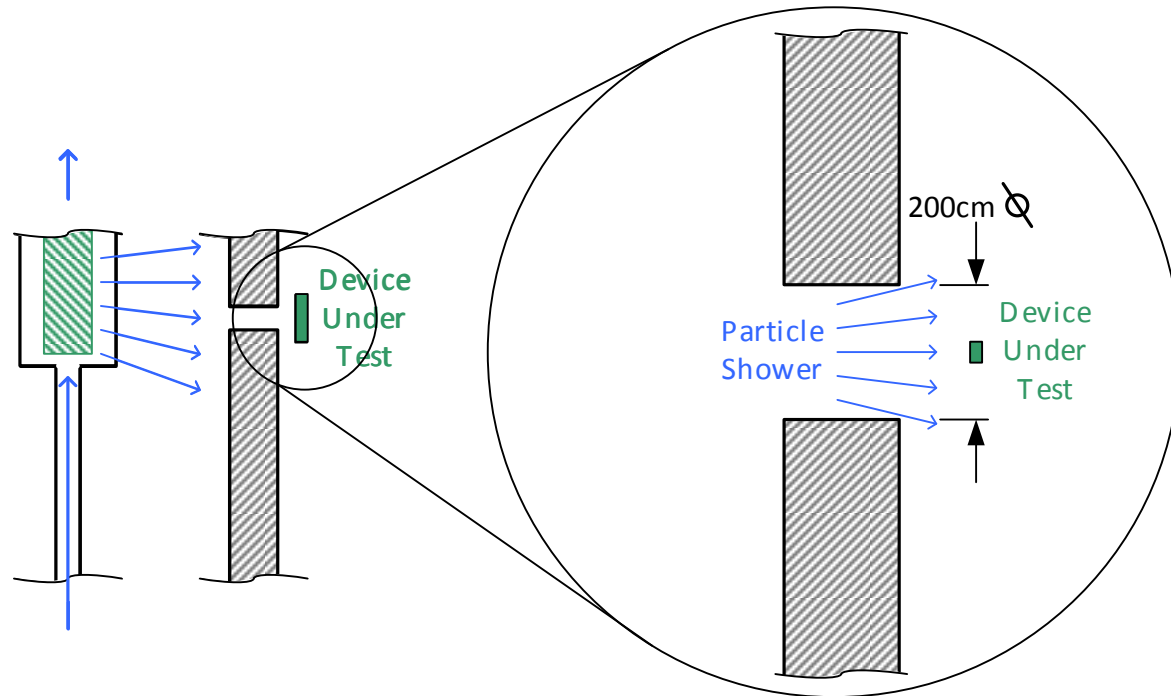
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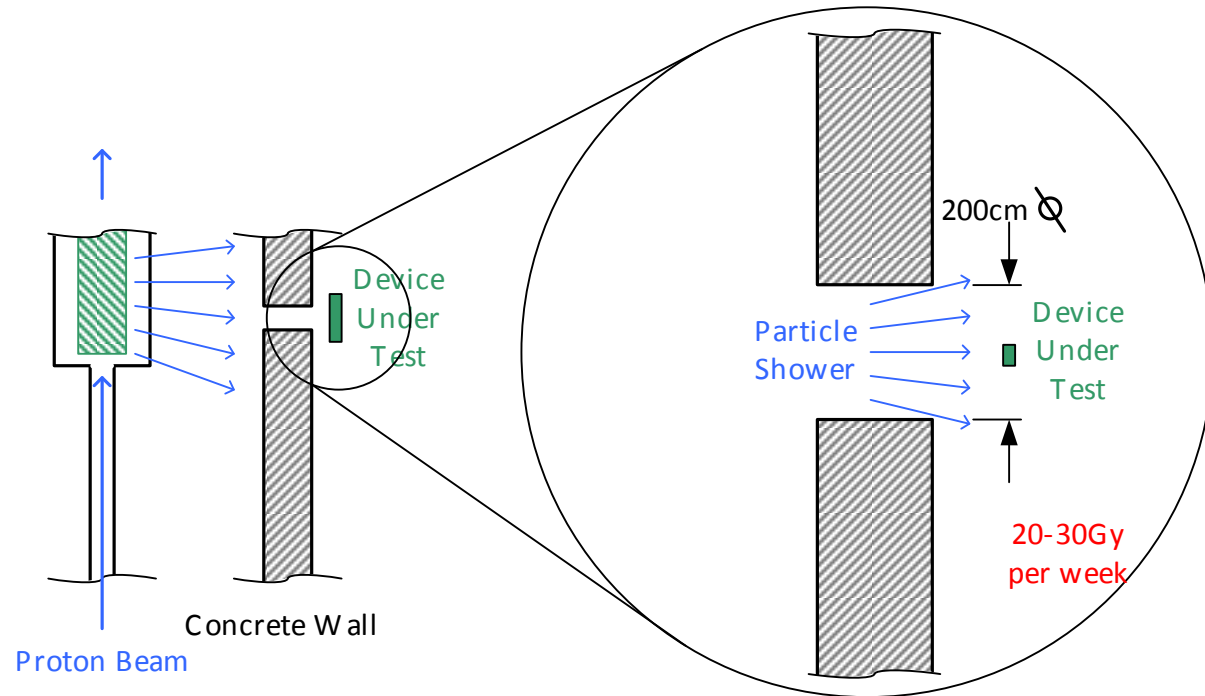
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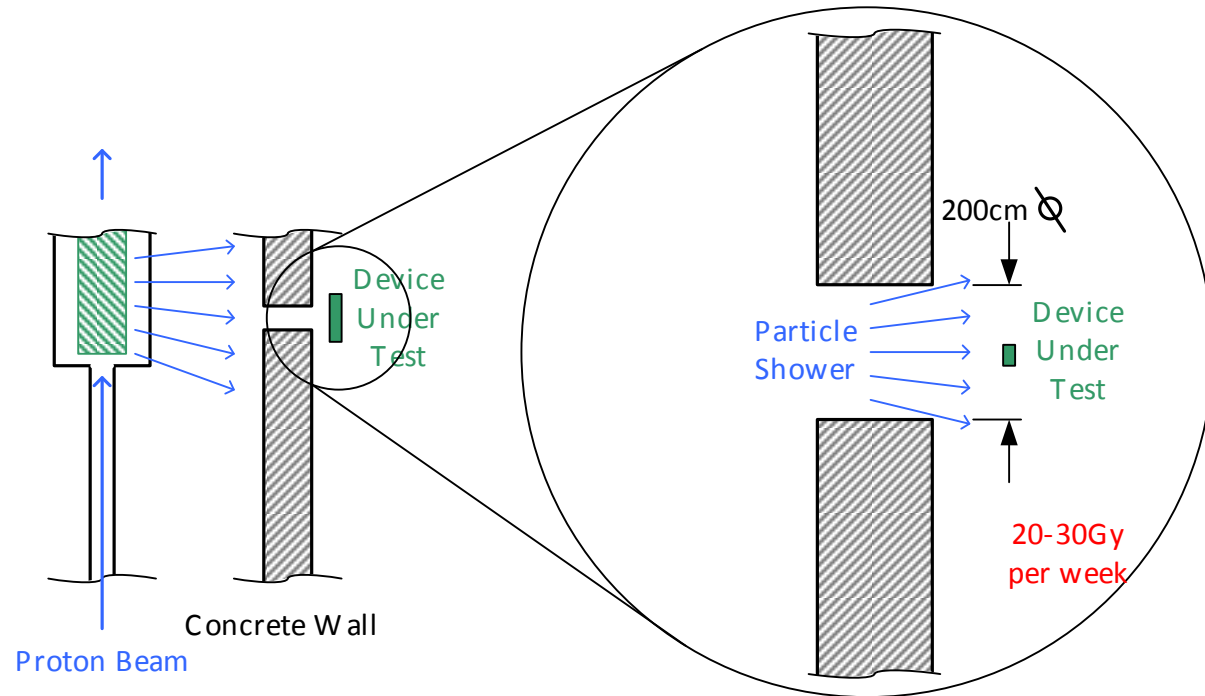
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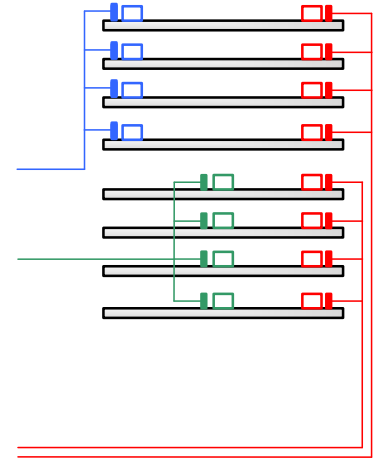
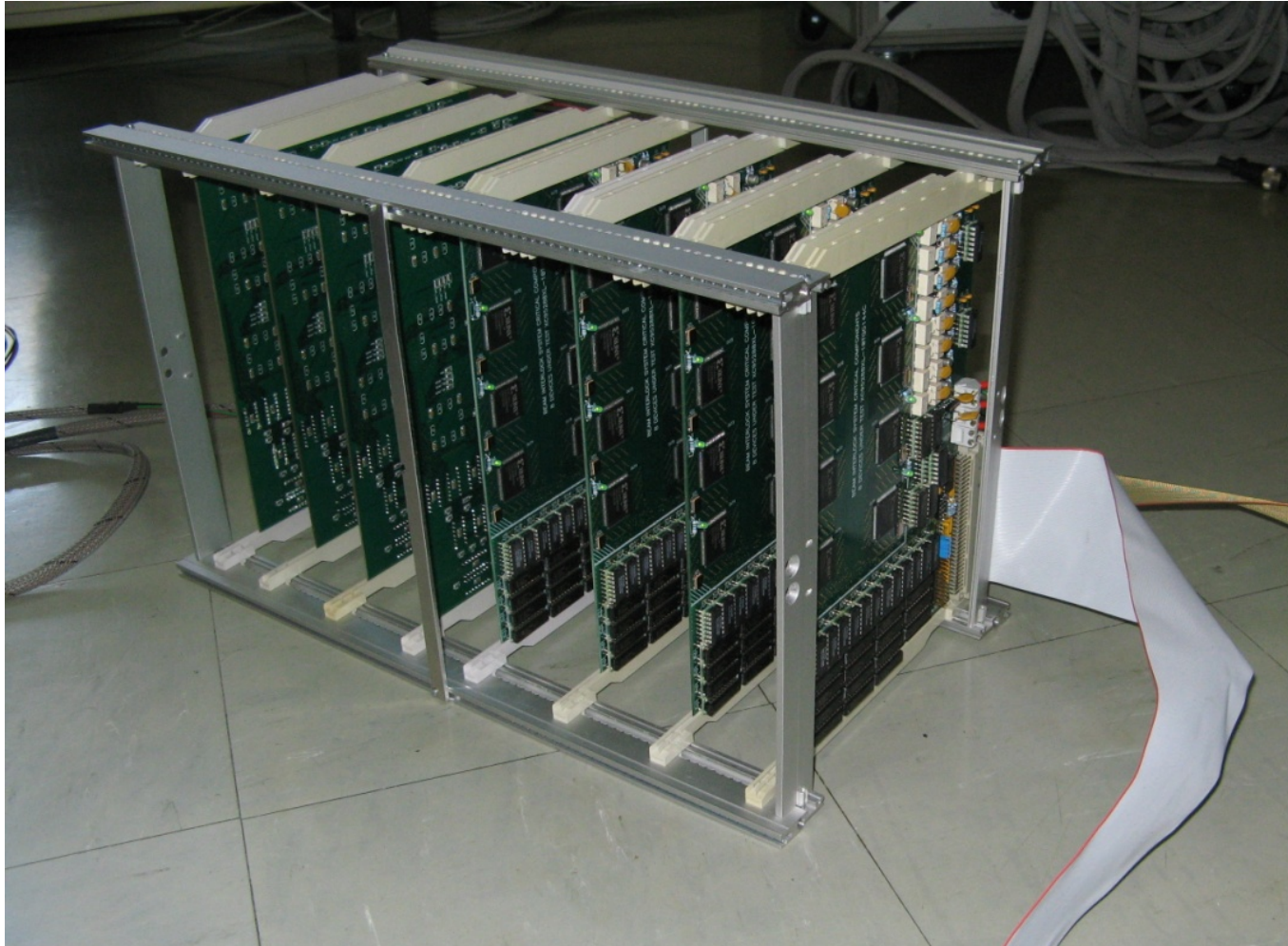


Principle for Test-bench "CIRX"

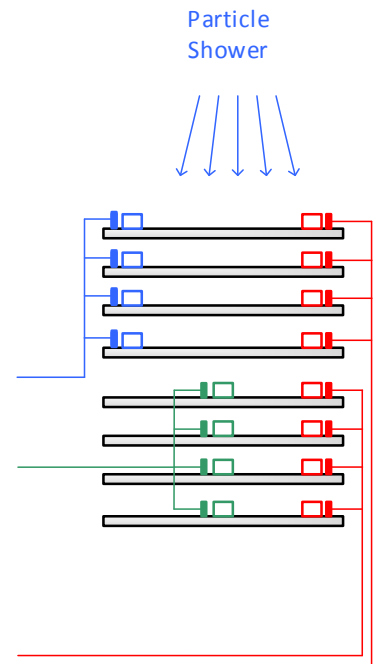


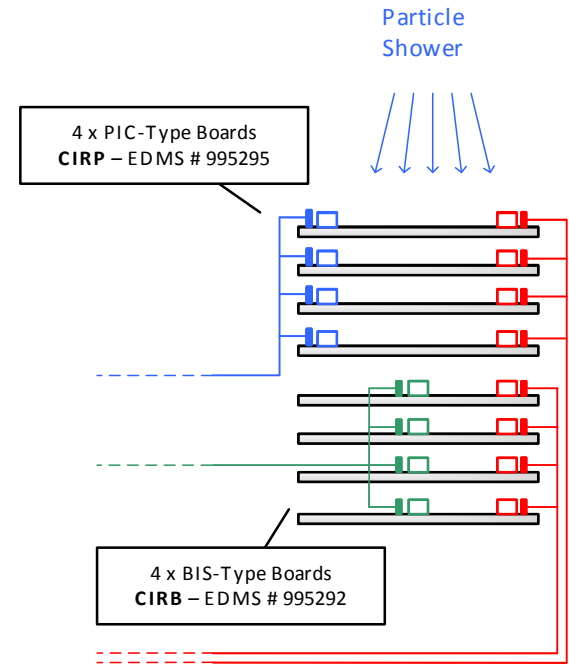
XC95144 x 32
XC95288XL x 32

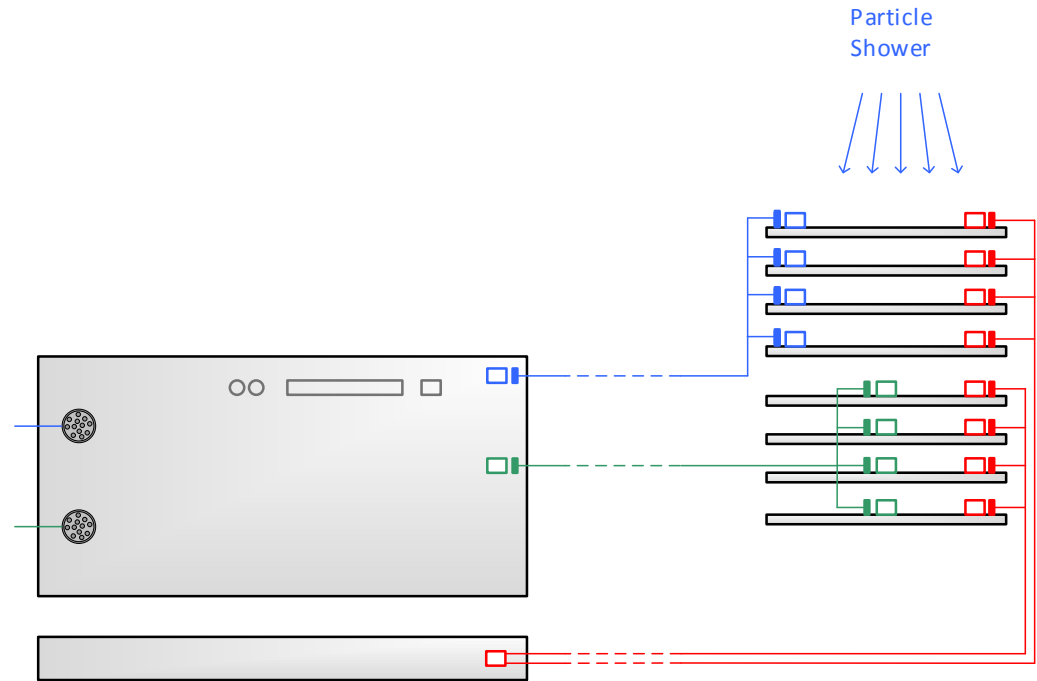
Testbench Electronic Functionality

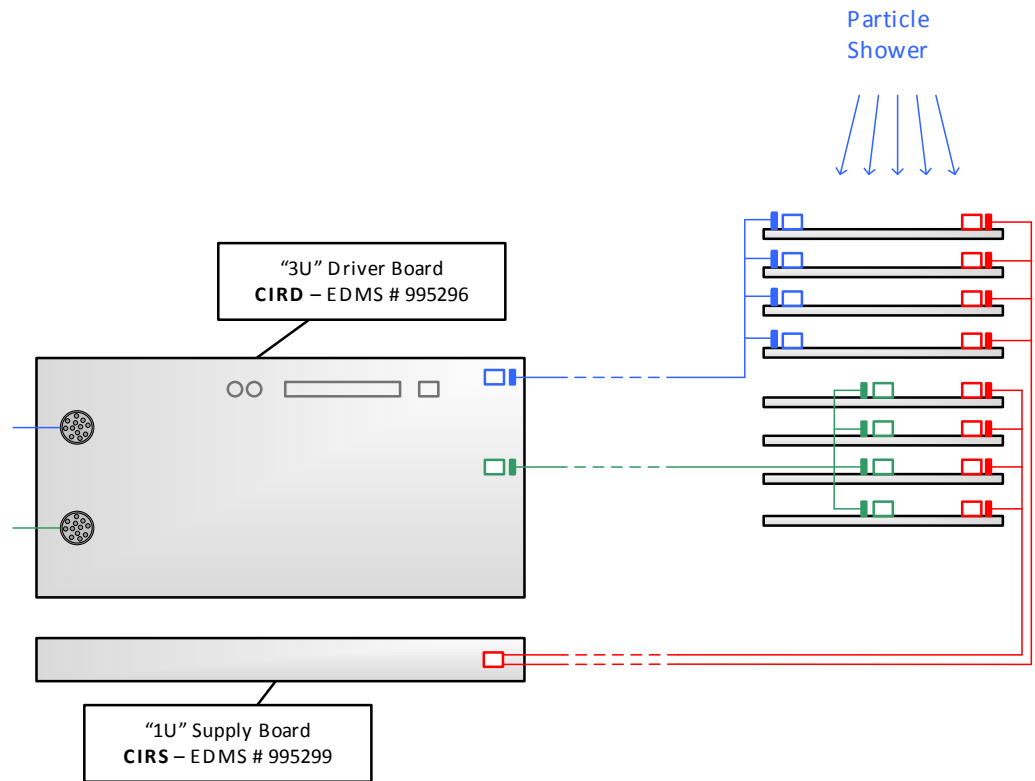


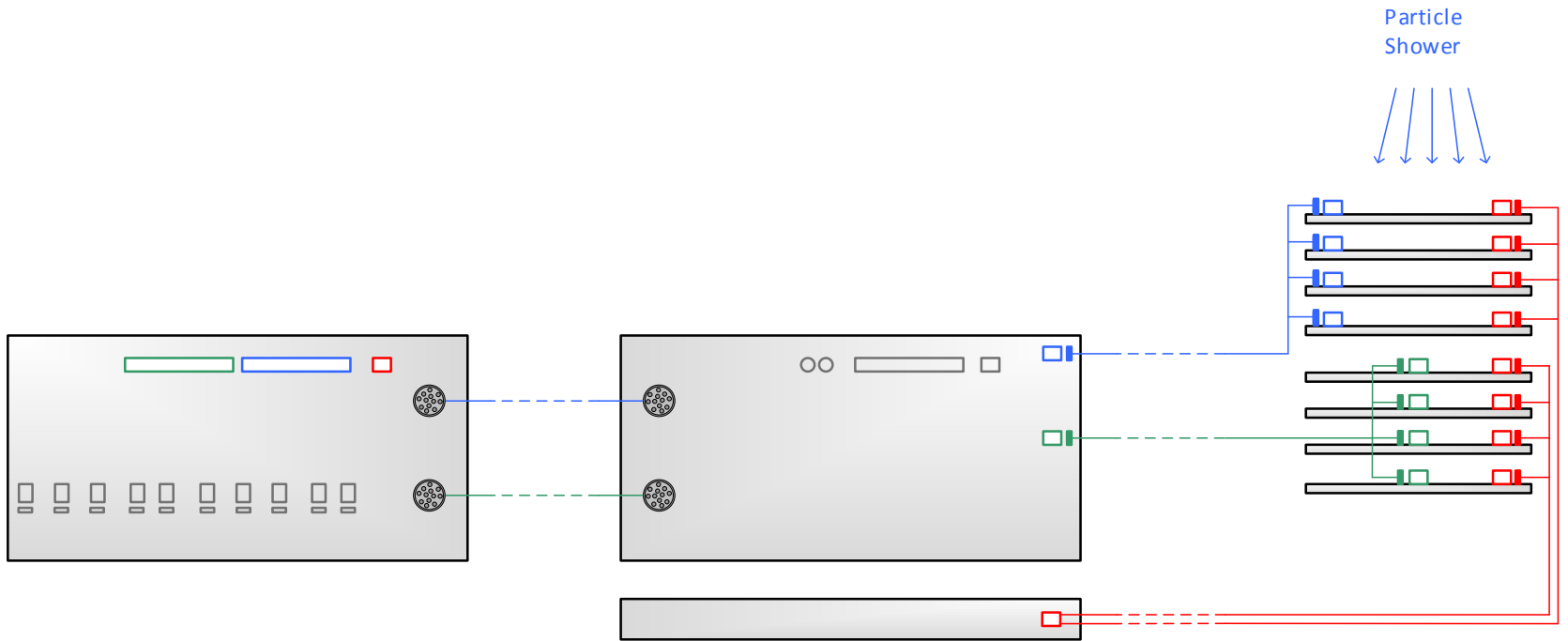
XC95144 x 32
XC95288XL x 32

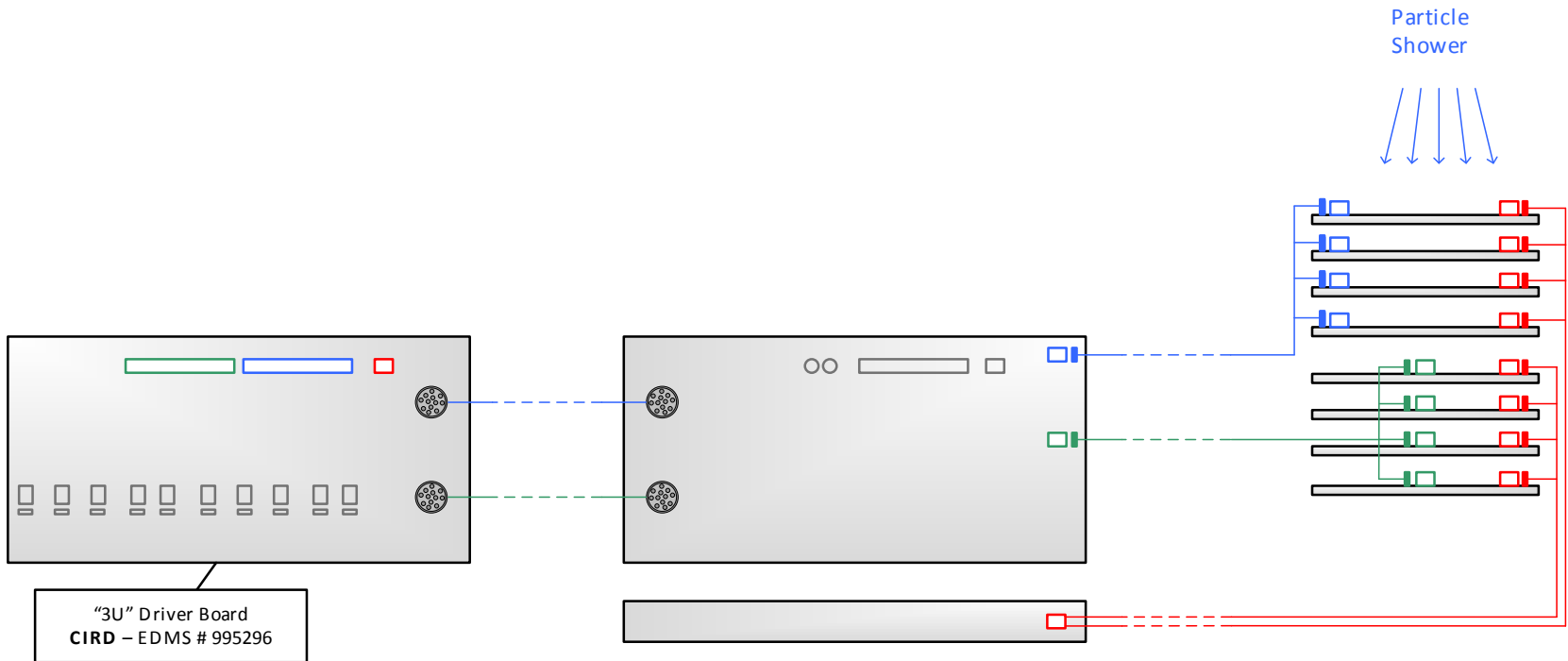


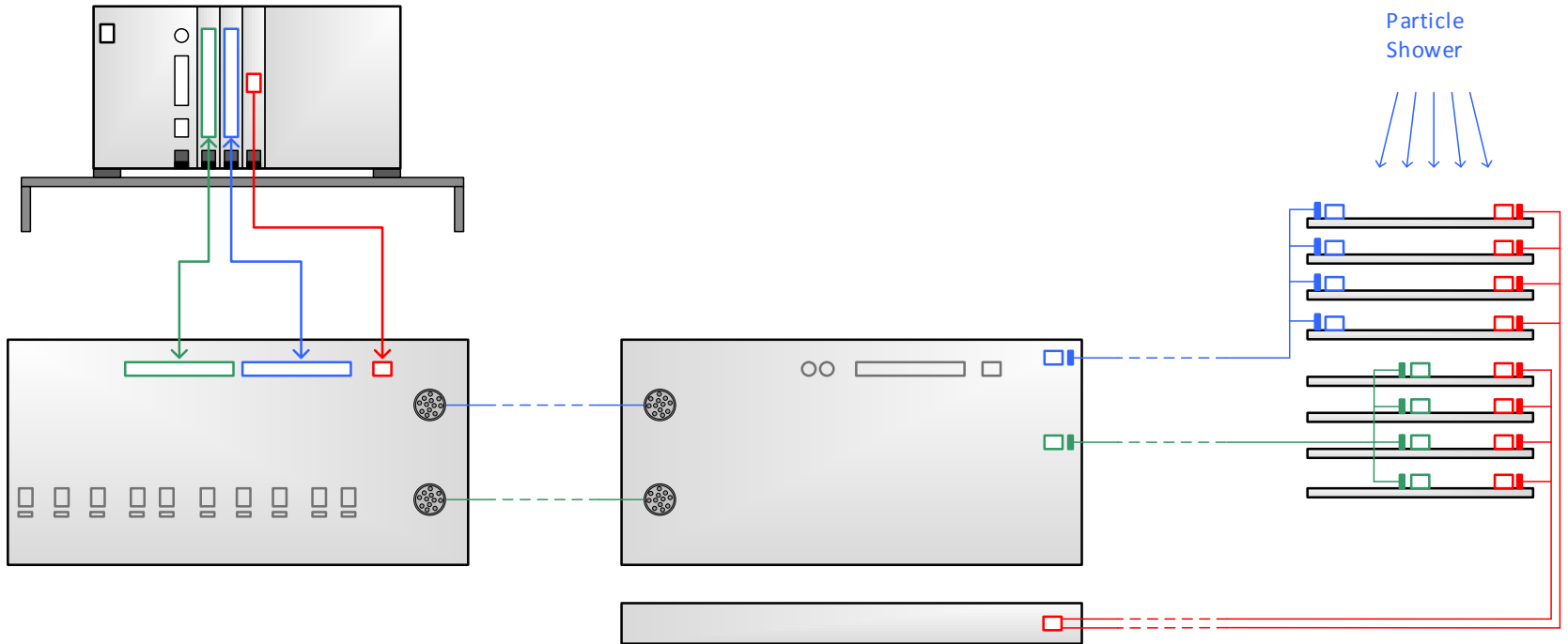




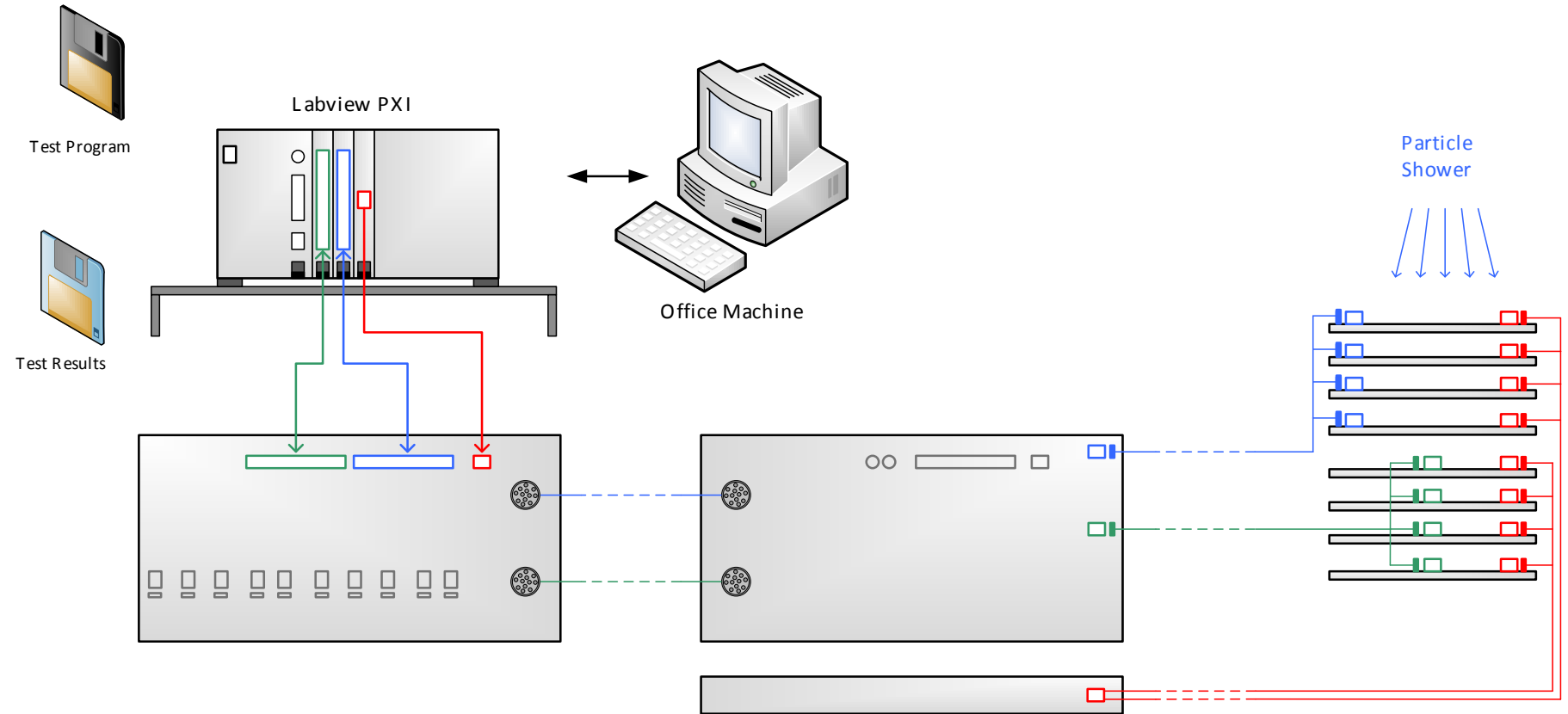




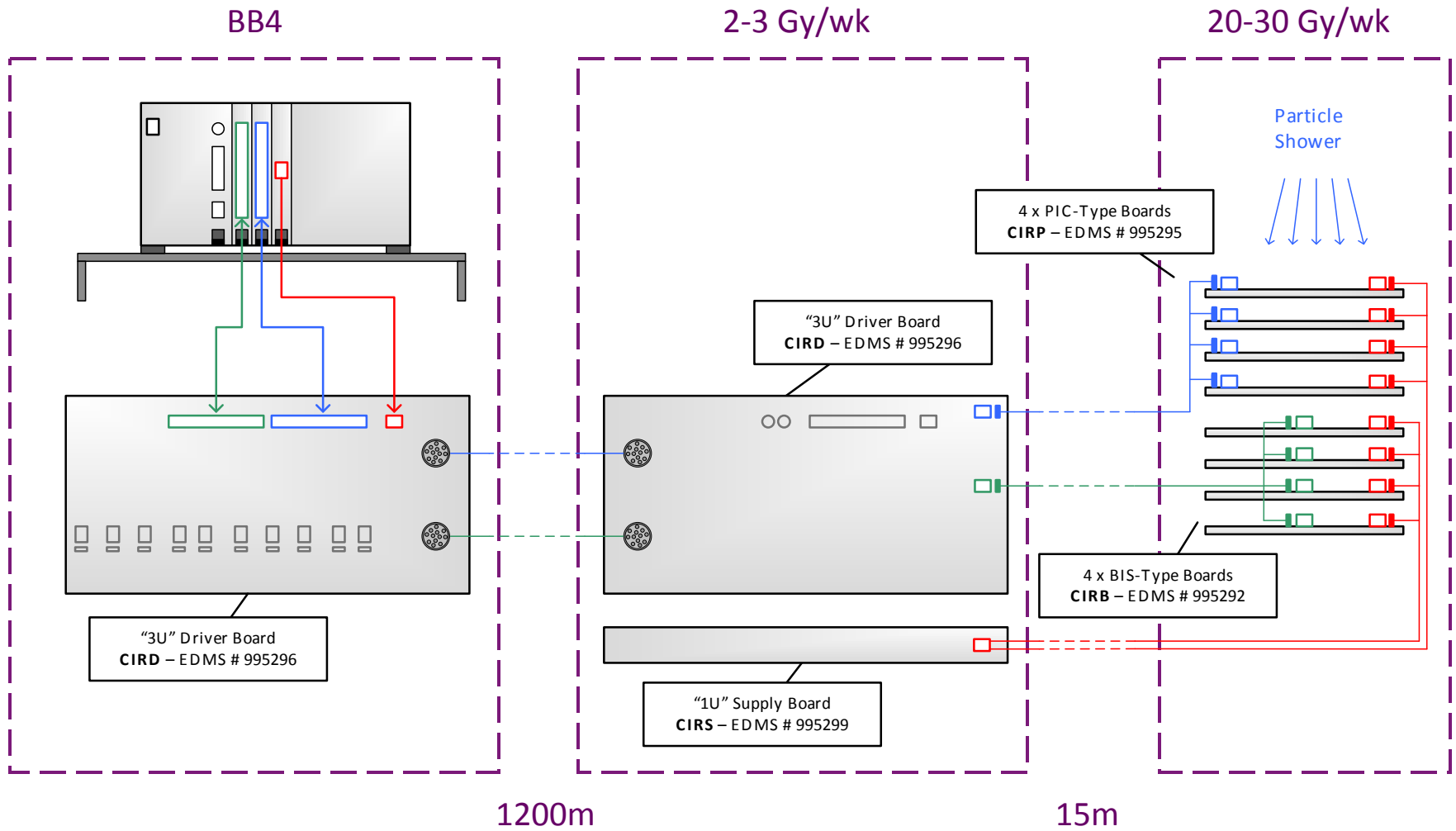


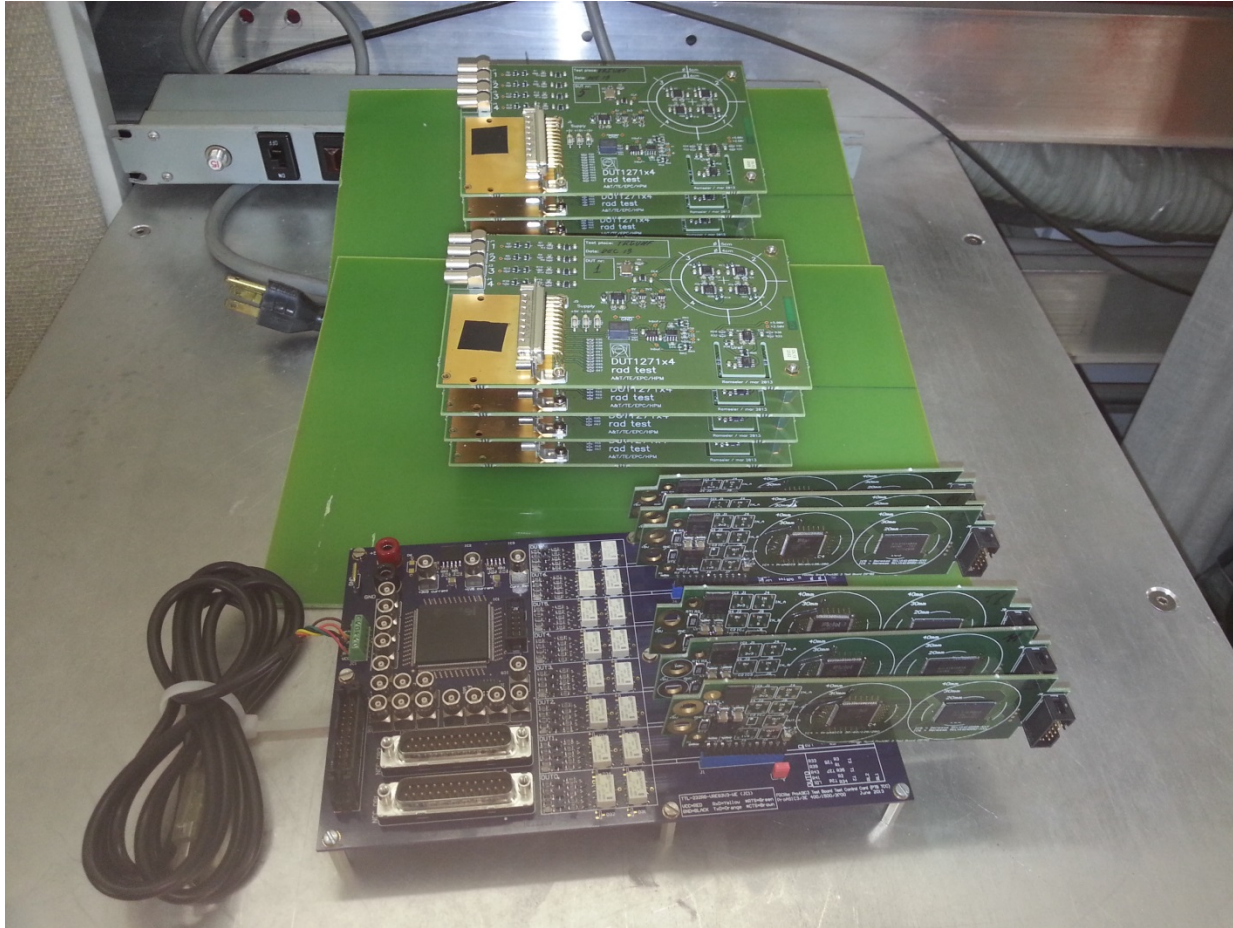


Testbench Electronic Functionality

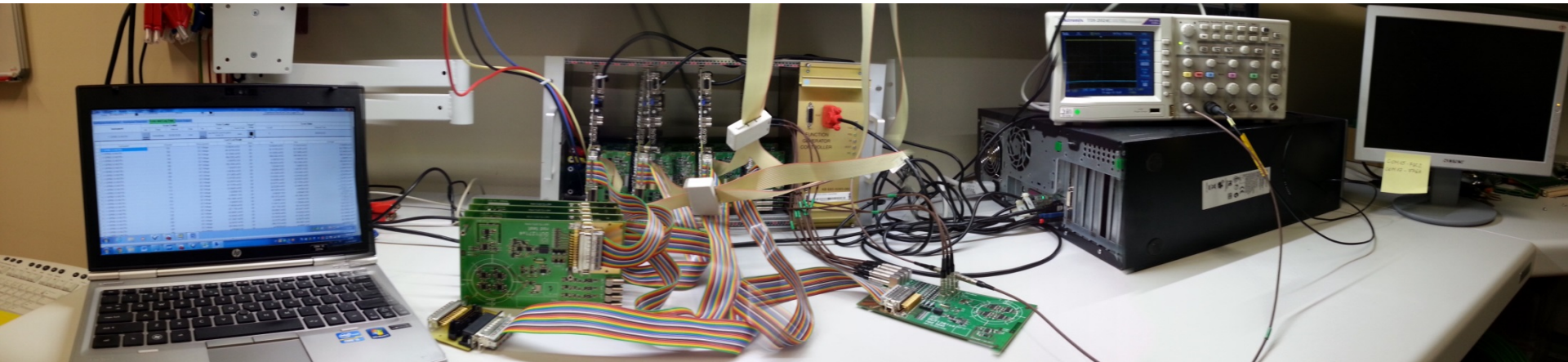


Testbench Electronic Functionality

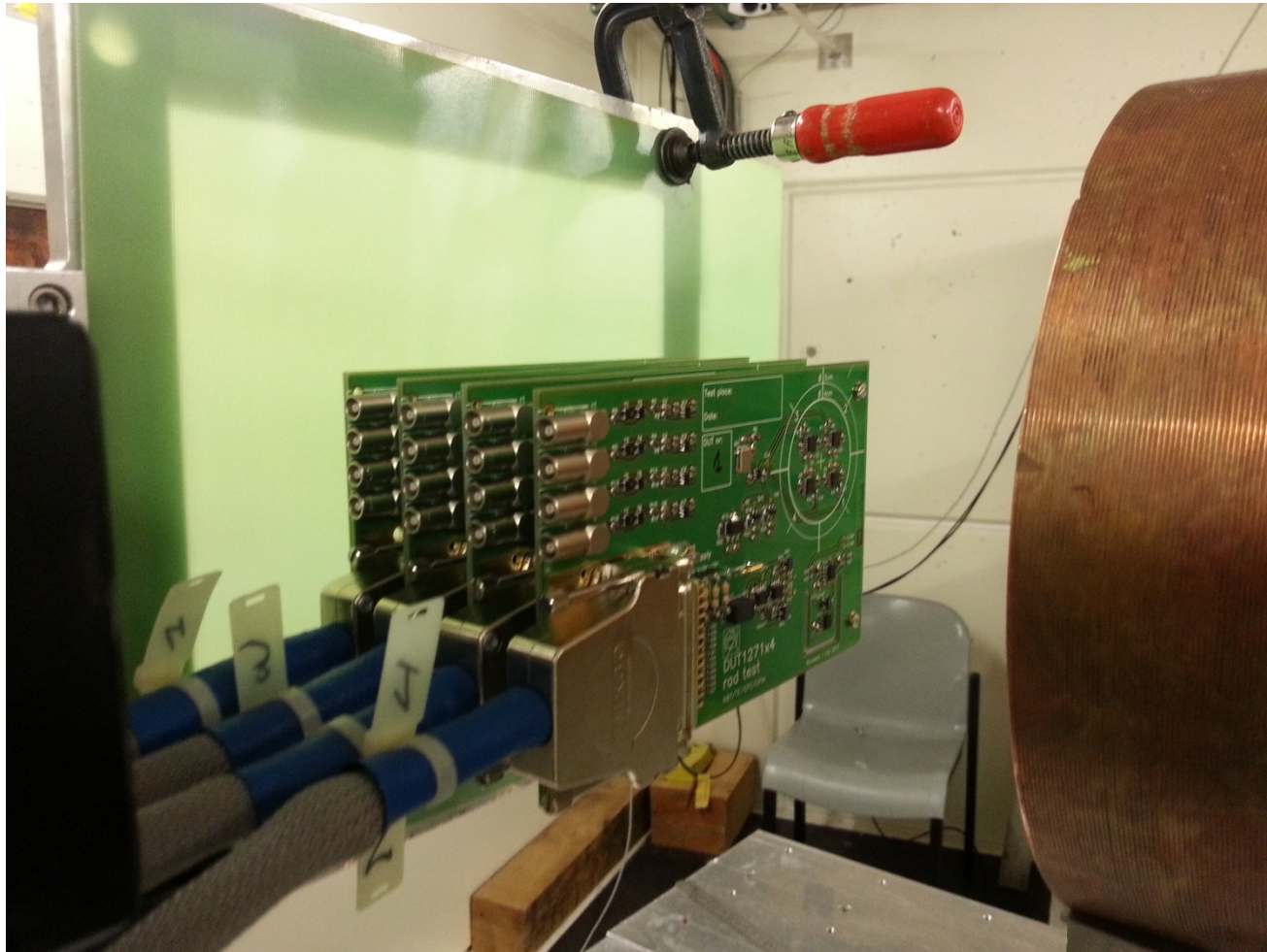




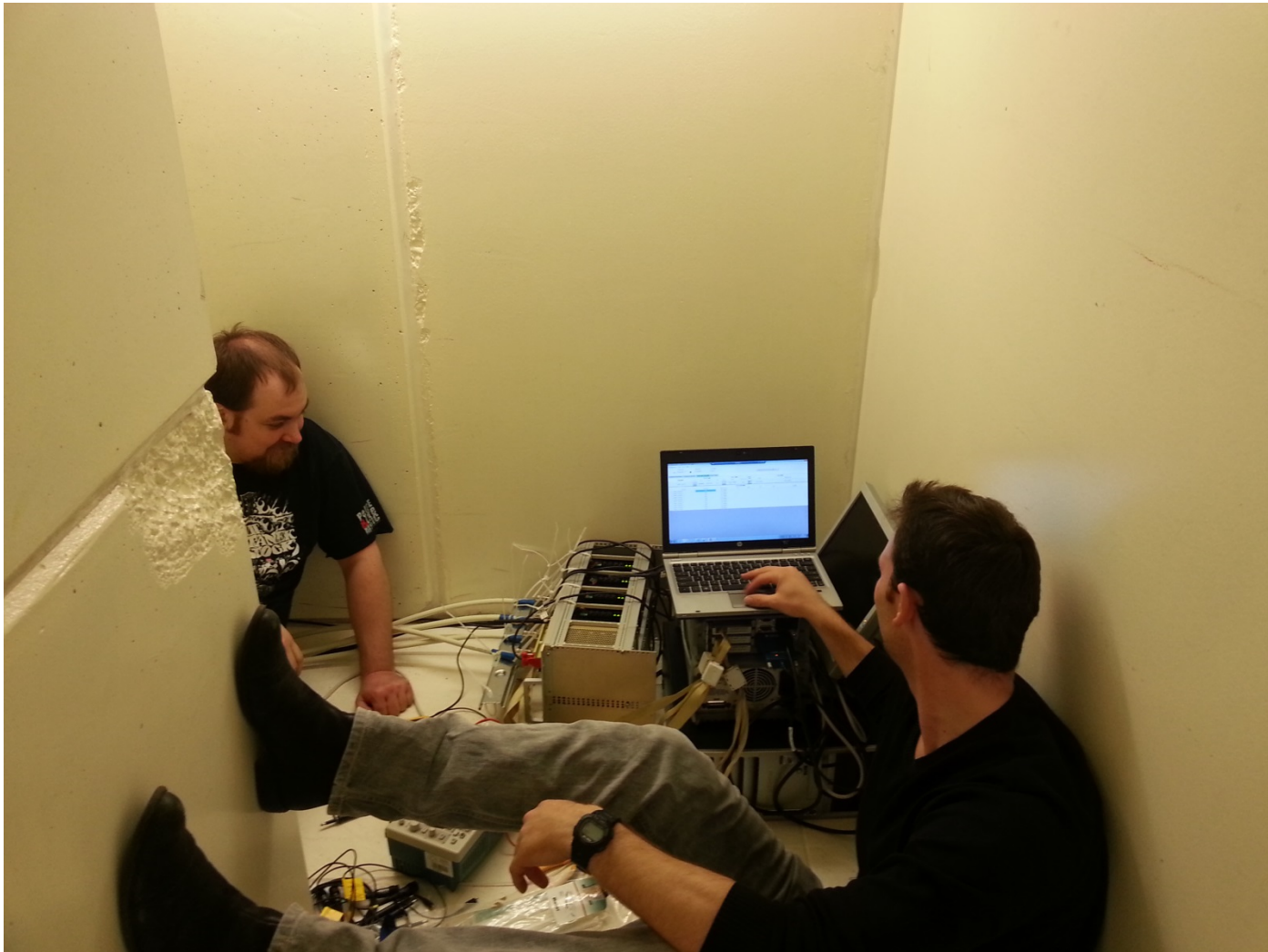
Every circuit which needs characterising needs a tester – here memory, FPGA and ADCs



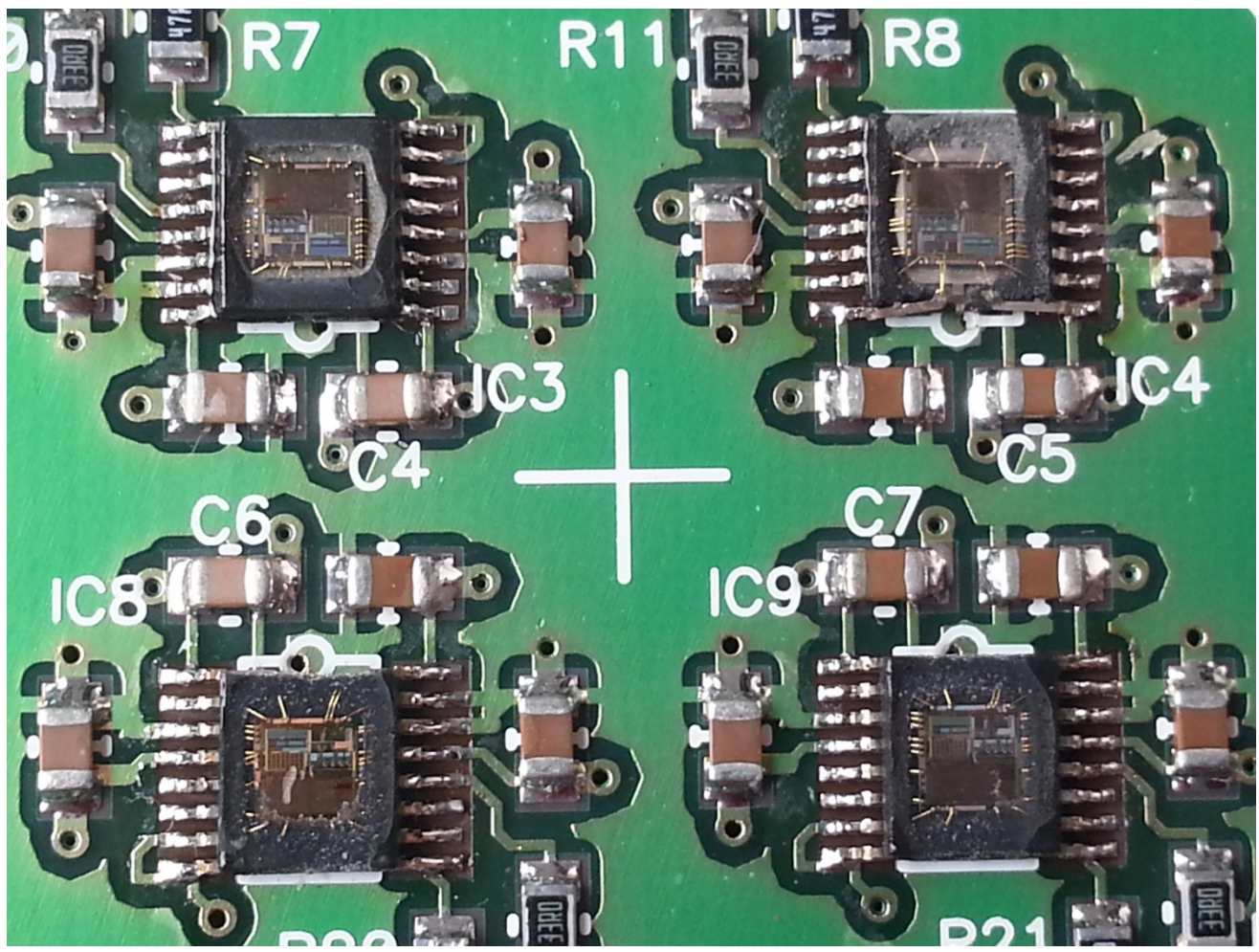
Every circuit which needs characterising needs a test infrastructure



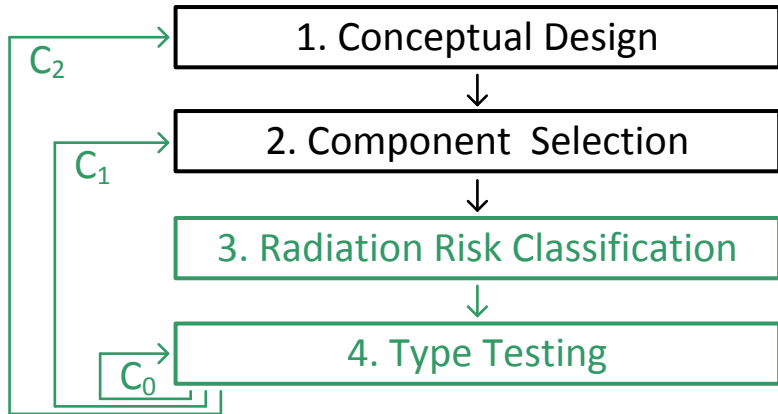
Then to be taken to a facility and tested = \$\$\$\$ and time+++

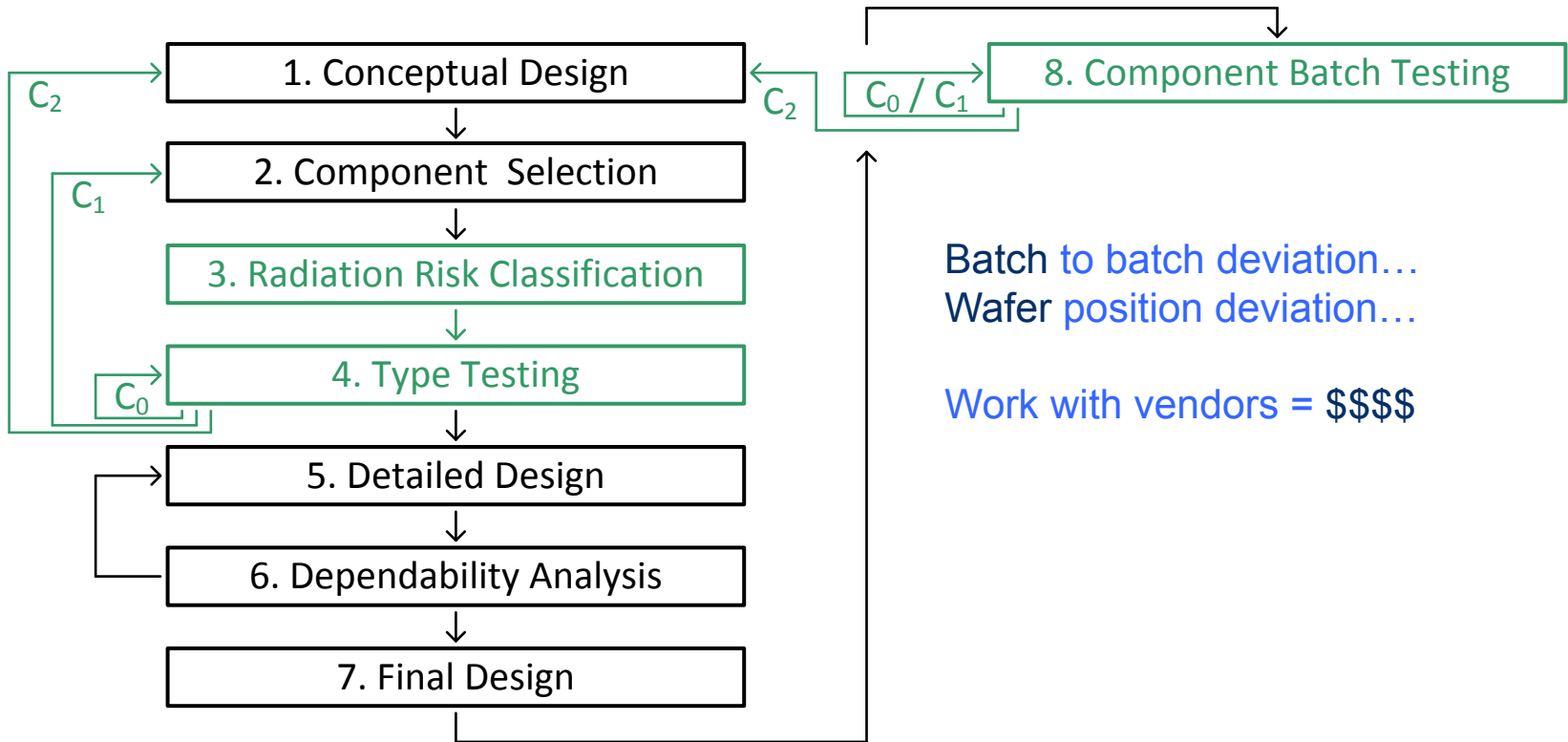


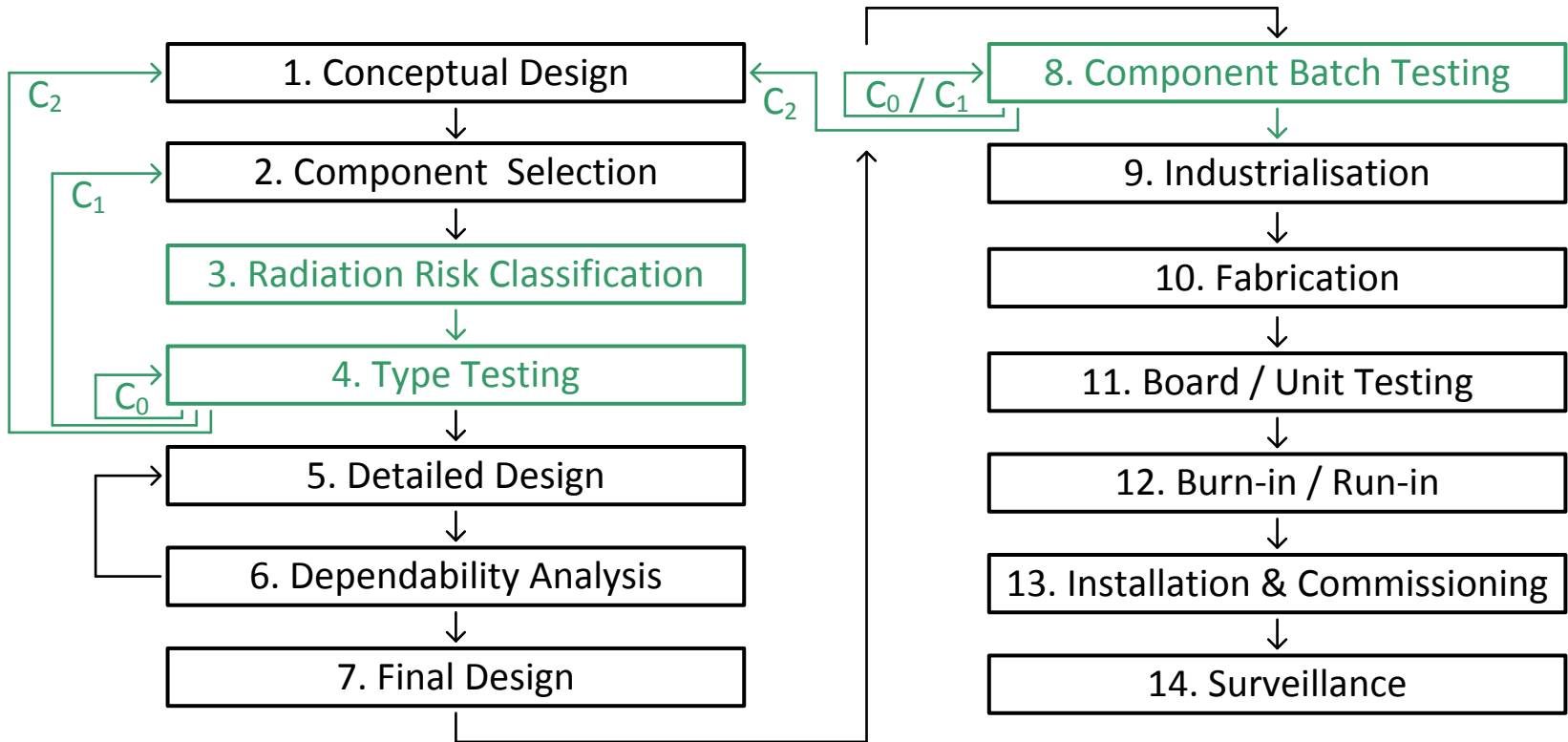
and a dedicated test team – who can make meaningful results



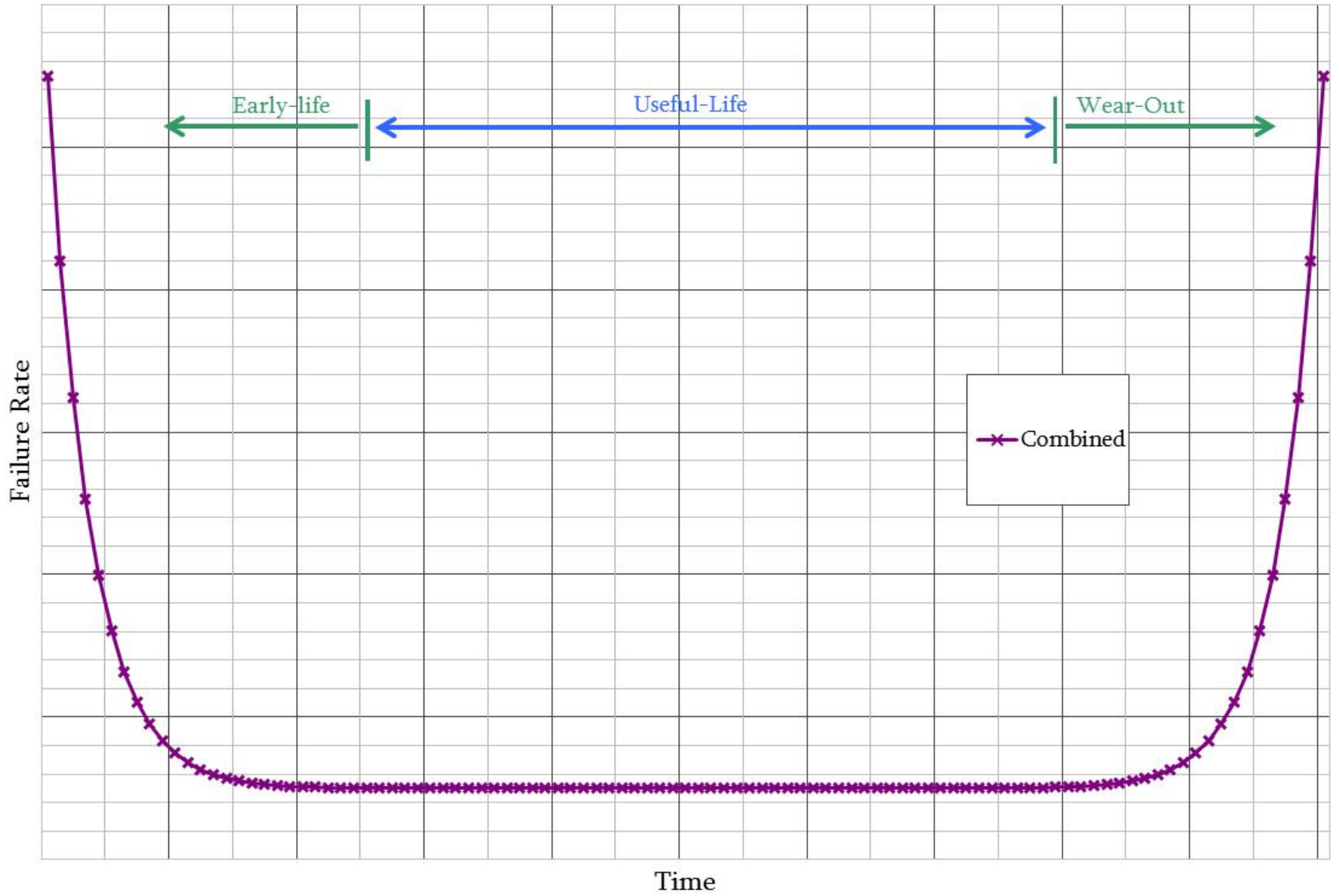
The packaging of components can effect interactions – here ADCs have had their plastic removed



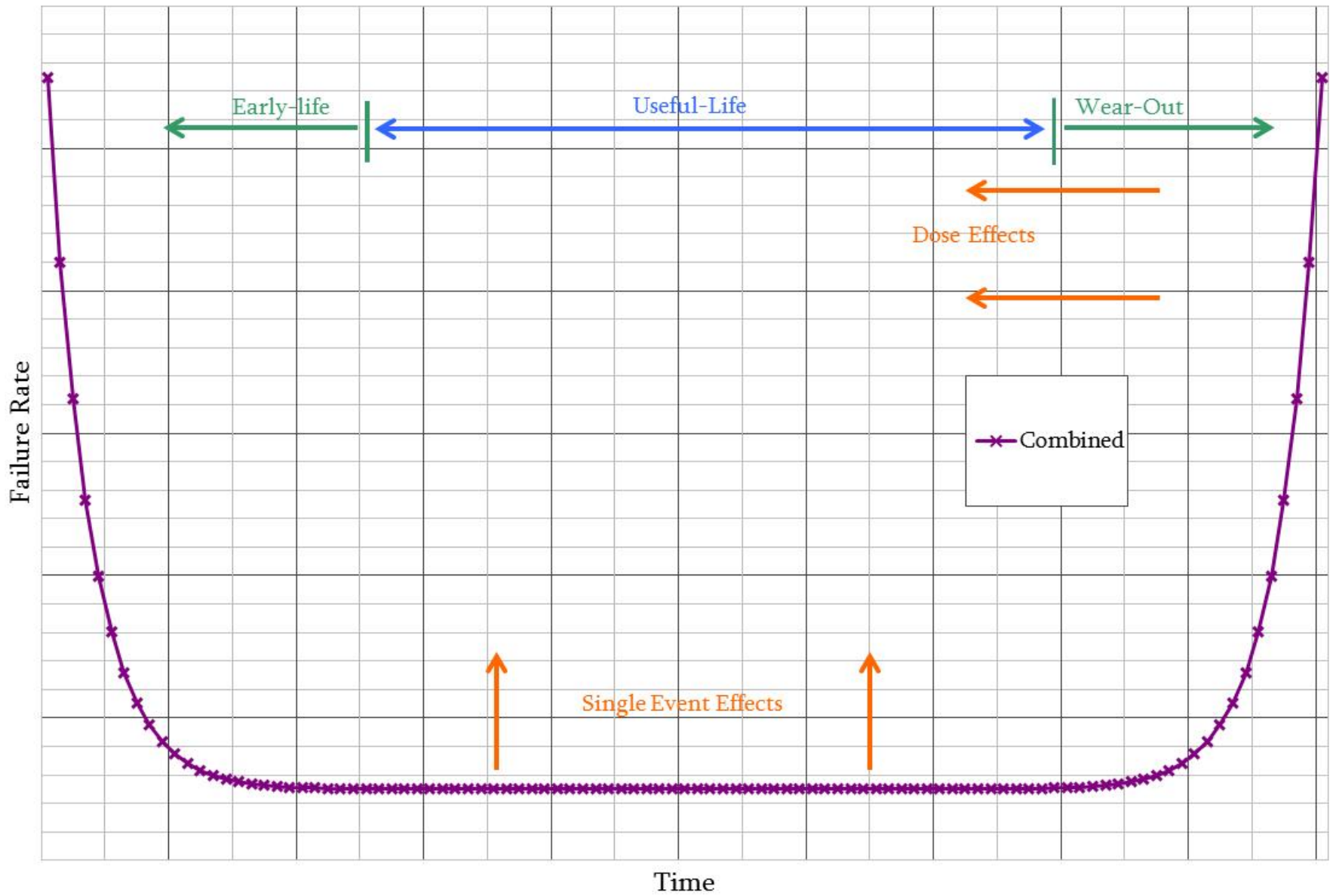




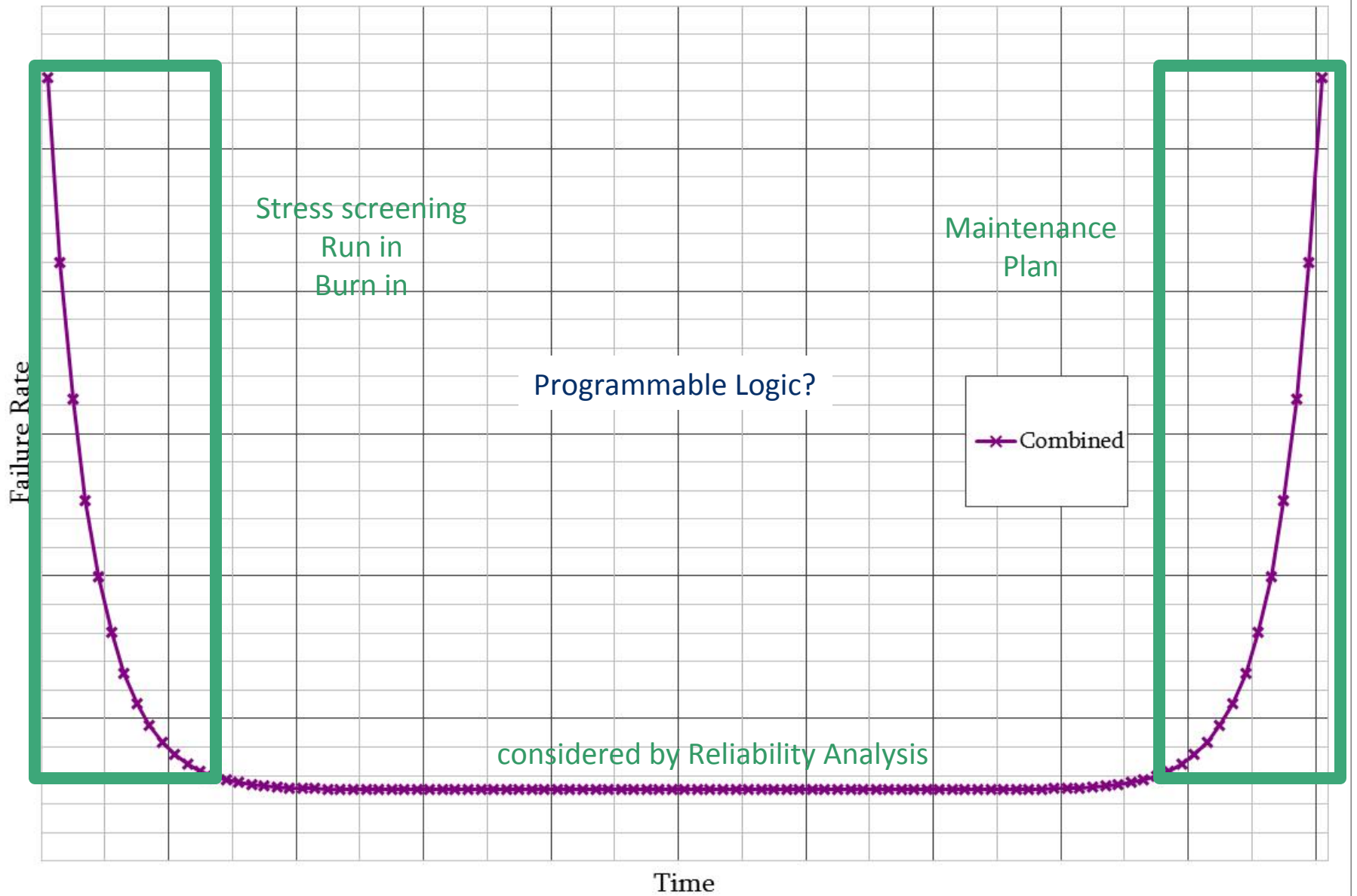
Qualitative Bathtub Curve



Qualitative Bathtub Curve



Qualitative Bathtub Curve



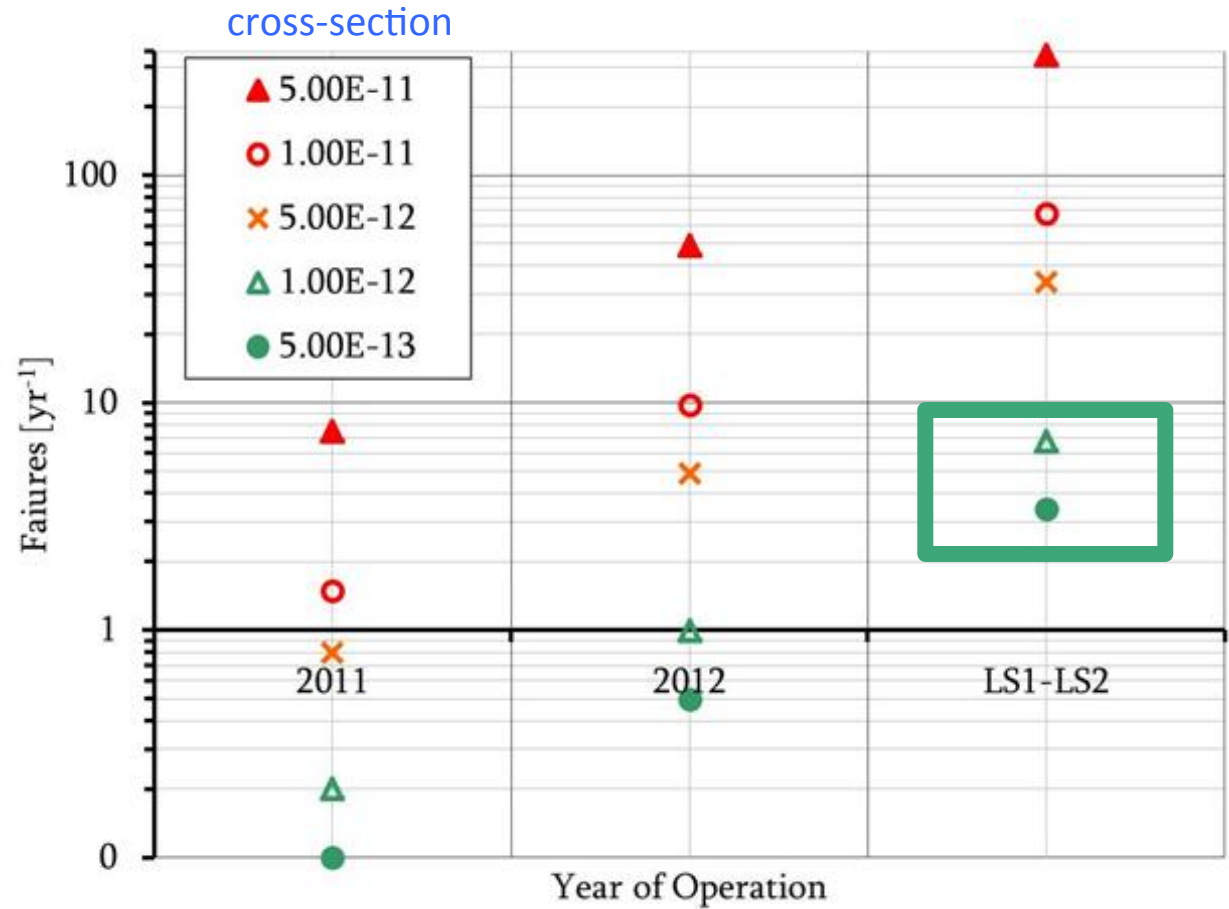
FGClite Reliability Requirements

acceptable failure rate < 40 per year...

Mean Time Between Failures > 200000 hours
 (1000 units x 8800 hours per year) / 40

cross-section < 1×10^{-12}
 > 300000 hours

SEE radiation
 electrical



FGClite Reliability Requirements

acceptable failure rate < 40 per year...

Mean Time Between Failures > 200000 hours

cross-section < 1×10^{-12}

> 300000 hours

SEE radiation

electrical

equipment lifetime > 25 years...

>200 Grays

design for 25 years

DD / TID radiation

electrical

In Conclusion...

- * radiation is everywhere, it can effect electronic systems
 - for dependable operation you cannot ignore this.
 - Particle accelerators actually create radiation fields.
 - certain failure modes are unique to radiation effects

As engineers building critical systems, you must consider the impact on your system

- * radiation effects on electronics are difficult and costly to characterise
 - by far the best thing to do is avoid exposure to radiation.

- 1) Remove the function if not possible then
- 2) Move away from the source “
- 3) Block radiation from the source “
- 4) Conceive a radiation tolerant system

- * radiation effects are difficult and costly to mitigate
 - by far the best thing to do is avoid exposure to radiation.

Take a closer look.

Fin!
Thank You!

- [1] M. Brugger and the R2E working group
<http://www.cern.ch/r2e>

- [2] From the Chamonix Performance Workshop 2011
<http://indico.cern.ch/conferenceOtherViews.py?view=standard&confId=103957>

- [3] Extracted from <http://lhc-statistics.web.cern.ch/LHC-Statistics/index.php>

- [4] Extrapolated from W. Herr's talk:
"Luminosity Performance Reach After LS1"

- [5] Derived from
<http://cdsweb.cern.ch/record/1123729/files/LHC-PROJECT-REPORT-1133.pdf?version=1>

- [6] Photographs courtesy Y. Thurel et al, from:
"LHC Power Converters the Proposed Approach"

- [7] Diagram background is from <http://cdsweb.cern.ch/record/842349/>

- [8] Figures and flow derived from work by Y. Thurel and S. Uznanski

- [9] Pictures courtesy S. Uznanski , K. Motala, CERN